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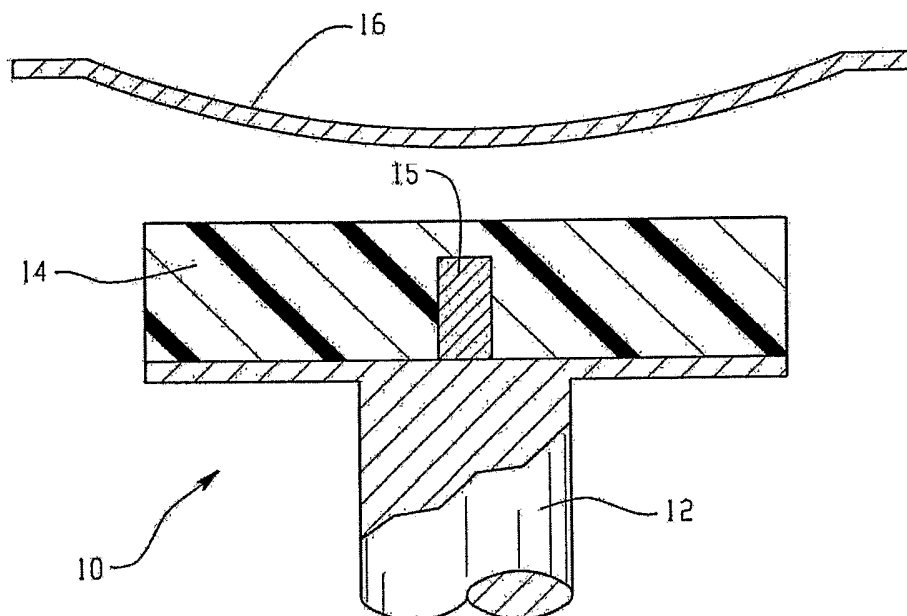
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[Continued on next page]

(54) Title: RECONFIGURABLE FIXTURE DEVICE AND METHODS OF USE



(57) Abstract: A fixture device (10) generally includes a base member (12), a reconfigurable pad (14) disposed on the base member (12), wherein the reconfigurable pad (14) comprises a shape memory material configured to selectively conform to a surface contour of a workpiece (16), and an activation device (24) in operative communication with the shape memory material. Also disclosed herein are computer program products as well as methods of using, controlling, and conforming the fixture device (10).



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RECONFIGURABLE FIXTURE DEVICE AND METHODS OF USE

BACKGROUND

[0001] The present disclosure generally relates to a flexible manufacturing system and, more particularly, to a reconfigurable fixture device for clamping and/or providing support for a variety of different workpiece configurations.

[0002] The advent of assembly lines has enabled rapid, mass production of products at a reduced product cost. Assembly lines typically include multiple operation stages and component, material, or sub-assembly inputs. Sometimes the workpieces are similar or related part shapes. Other times, the workpieces are of unrelated design but require similar manufacturing operations. In these varied applications, the fixture reconfiguration or changeover from one part design to another has to be fast enough to meet the productivity requirements of current manufacturing systems.

[0003] Previous efforts in designing and developing flexible fixturing for either small batch manufacture or mass production scenarios can generally include the use of modular fixtures and conformable fixtures. Modular fixturing generally includes fixtures assembled from a standard library of elements such as V-blocks, toggle clamps, locating blocks, and the like. Their flexibility lies in the ability to be reconfigured either manually or by a robotic device. However, modular fixtures have no intrinsic ability to adapt to different sizes and shapes of parts within a part family. In addition, the time necessary for reconfiguration is long. As a result, modular fixtures are more suited to a job shop environment than mass production.

[0004] The advent of Flexible Manufacturing Systems (FMS) in the early 1960's provided the impetus for work on conformable fixturing. A conformable fixture is defined as one that can be configured to accept parts of varying shape and size. Conformable fixture technology generally includes encapsulant or mechanistic techniques. Examples of encapsulant fixtures are found in the aerospace industry,

where low melting-point metals are used to enclose turbine blades and produce well-defined surfaces for part location and clamping for grinding operations. While an excellent means of facilitating the holding of complex parts, encapsulation is a costly and time-consuming process.

[0005] Mechanistic fixtures reported in the literature include the use of petal collets, programmable conformable clamps, a programmable/multi-leaf vise, and an adjustable integral fixture pallet. Of the four, the adjustable integral fixture pallet concept appears to be the most capable of accommodating a part family of castings. To date, however no feasibility studies have been conducted regarding the applicability of any of these techniques to production machining operations.

[0006] One troublesome area in flexible manufacturing systems is its implementation in body shops. Clamps are typically employed to clamp the various sheet metal workpieces (e.g., body panels) during assembly and clamping can potentially scratch the exposed surface and/or locally deform the workpiece or surface coating, affecting its aesthetic quality. While, ideally, clamping could be performed on flanges or surfaces that are invisible or immaterial to end users, some clamping inevitably occurs on surfaces whose quality is important aesthetically.

[0007] Current clamps utilized in assembly lines generally include a metal (e.g., tool steel) clamp block, which accurately matches the contours of the workpiece and a matching pressure foot. In operation, the clamp block with a contoured surface supports the exterior surface of the workpiece while the pressure foot contacts the inner (non-exposed) surface. As a result, the contour of each clamp block is generally specific to a limited number of workpieces. In dedicated facilities, the contours of the clamp block are generally fabricated by numerically controlled (NC) machining using data generated from the workpiece to be fixtured. A problem arises if multiple models having significantly different workpiece configurations are to be produced on the same tooling setup. Multiple clamp blocks having different contours are then required to accommodate the multiplicity of workpiece configurations.

[0008] Clamps with a compliant pad and a matching pressure foot are also used in assembly lines for fixturing workpieces with aesthetically important surfaces.

In operation, the clamp block with a contoured surface supports the exterior surface of the workpiece while the pressure foot contacts the inner (non-exposed) surface. The compliance of the clamp block ensures that the surface is not marked and the rigidity of the pressure foot ensures that the location of the part is known completely (to within the tolerance imposed by the deformation of the part under the clamp loads), i.e., the part is not floating with regard to the clamp block. With this approach, minor differences between the shape of the workpiece and the clamp block geometry can be accommodated without introducing local deformation. As a result, the contour of each clamp block is generally specific to a limited number of workpieces. In dedicated facilities, the contours of the clamp block are generally fabricated by numerically controlled (NC) machining using data generated from the workpiece to be fixtured. A problem arises if multiple models are produced having significantly different workpiece configurations. Multiple clamp blocks having different contours are then required to accommodate the multiplicity of workpiece configurations.

[0009] Accordingly, there remains a need for a reconfigurable fixture device that can provide adequate support and/or clamping means for a variety of workpiece configurations.

BRIEF SUMMARY

[0010] Disclosed herein are fixture devices, computer program products, as well as methods of using, controlling, and conforming the fixture devices. The fixture device generally includes a base member, a reconfigurable pad disposed on the base member, wherein the reconfigurable pad comprises a shape memory material configured to selectively conform to a surface contour of a workpiece, and an activation device in operative communication with the shape memory material.

[0011] The above described and other features are exemplified by the following figures and detailed description.

BRIEF DESCRIPTION OF THE DRAWINGS

[0012] Referring now to the figures, which are exemplary embodiments and wherein the like elements are numbered alike:

[0013] Figure 1 is a cross sectional view of a fixture device prior to setting the configuration of the reconfigurable pad;

[0014] Figure 2 is a cross sectional view of the fixture device of Figure 1 during the setting of the configuration of the reconfigurable pad so as to conform to a surface of a workpiece;

[0015] Figure 3 is a cross sectional view of the fixture device of Figure 1 upon removal of the workpiece after setting the configuration of the reconfigurable pad;

[0016] Figure 4 is a cross sectional view of the fixture device of Figure 1 after resetting the reconfigurable pad to its original configuration;

[0017] Figure 5 is a cross sectional view of a fixture device with a composite reconfigurable pad;

[0018] Figure 6 is a cross sectional view of a fixture device adapted for gripping and/or clamping a workpiece, wherein the respective reconfigurable pads are set to conform to the surface of the workpiece;

[0019] Figure 7 is a cross sectional view of the fixture device of Figure 6 upon release of the workpiece;

[0020] Figure 8 is a cross sectional view of a fixture device employing a thermoelectric unit in accordance with one embodiment;

[0021] Figure 9 is a cross sectional view of a fixture device employing a thermoelectric unit in accordance with another embodiment; and

[0022] Figure 10 is a flow chart of an exemplary control process for a fixture device system.

DETAILED DESCRIPTION

[0023] Disclosed herein are reconfigurable fixture devices for providing support and/or securement of a variety of dissimilar workpieces such as may be desired for a flexible manufacturing system. Suitable workpieces for loading onto the

fixture device are those that are sufficiently rigid so as not to flex or distort under the weight of the workpiece or by any clamping force (which can be as high as 500 pounds distributed over roughly 1 square inch) when using the fixture device. Although reference will be made to its use in fixturing body panels for motor vehicles (e.g., cars, trucks, motorcycles, boats, airplanes, and the like), it should be understood that the reconfigurable fixture devices could be employed for a variety of end use applications where it may be desirable to support and/or clamp dissimilar workpieces using the same tooling setup without requiring manual adjustment or reprogramming. For example, the reconfigurable fixture devices can be employed for fixturing thin walled and/or thick walled objects, contoured and/or planar objects, on exterior surfaces as well as on hidden surfaces, and the like.

[0024] It will be apparent to those skilled in the art in view of this disclosure that the reconfigurable fixture devices disclosed herein can advantageously be used on exposed surfaces of body panels without marring, scratching, and/or causing local deformations such as may be required for assembly of parts having Class A surfaces. Class A surfaces are generally external surfaces that are visible to an end user (e.g., a door, fender, hood, trunk, hull, interior trim, and the like). In contrast, Class B and C surfaces are generally surfaces not normally seen by the end user and have fewer requirements in terms of tangency and surface defects.

[0025] Referring now to Figures 1-9, there are shown cross-sectional views of exemplary reconfigurable fixture devices, generally designated by reference numeral 10, in varying types and/or stages of fixturing. The reconfigurable fixture device 10 can be employed as a supporting device (e.g., as shown in Figures 1-5 and 8-9) or as a clamping device (e.g., as shown in Figures 6-7) depending on the desired application. As such, the term "fixture device" includes devices intended for clamping applications as well as for supporting applications.

[0026] Also, the terms "first", "second", and the like do not denote any order or importance, but rather are used to distinguish one element from another, and the terms "the", "a", and "an" do not denote a limitation of quantity, but rather denote the presence of at least one of the referenced items. Furthermore, all ranges reciting the

same quantity or physical property are inclusive of the recited endpoints and independently combinable.

[0027] The reconfigurable fixture device 10 for clamping and/or supporting workpieces 16 generally includes a base member 12 upon which is disposed a reconfigurable pad 14. The fixture device 10 can be fixed in space such as by hard tooling or may be adapted for use with programmable multi-axis tooling device (e.g., robotics, and the like). In supporting applications (i.e., Figures 1-5 and 8-9), the fixture device 10 includes a (i.e., at least one) reconfigurable pad 14, which can be utilized during processing to support the workpiece. Alternatively, in clamping applications (Figures 6-7), a (i.e., at least one) pair of opposing pads (e.g., one for a clamp block and one for an opposing pressure foot) are employed, wherein one or both of the pads are reconfigurable in the manner that will be described in greater detail below. For example, a fixture device can be employed for clamping a workpiece 16 in which only the pad contacting the Class-A surface of the workpiece is reconfigurable while the opposing pad that contacts a non-Class A surface is not. In other clamping application embodiments, such as those shown in Figures 6-7, it may be desirable that both pads are reconfigurable.

[0028] Hereinbelow, for convenience, when reference is made to a reconfigurable pad 14, the reconfigurable pad 14 being described may be the reconfigurable pad 14 used for a supporting fixture device 10 and/or it may be one or both (depending on the application) of the opposing reconfigurable pads 14 used for a clamping fixture device 10.

[0029] Optionally, the base member 12 may have a plurality of reconfigurable pads 14 disposed thereupon. One or more than one of the plurality of reconfigurable pads 14 may be used to fixture a single workpiece 16 at the same time. In one embodiment, each of the reconfigurable pads 14 is indexed (i.e., each of the plurality of reconfigurable pads 14 can be configured to a specific range of workpiece 16 shapes) and the base member 12 may be rotated or moved to place the appropriately indexed reconfigurable pad 14 in position to fixture the workpiece. Training of the reconfigurable pads can be online or offline depending on the desired configuration and/or application.

[0030] Optionally, the fixture device 10 further comprises a locator pin 15 disposed on the base member 12, within and/or adjacent to the reconfigurable pad 14. The locator pin 15 desirably remains in a fixed position with respect to the base member 12. The locator pin 15 can be used to provide information as to the location of the workpiece 16 during operation of the fixture device 10. While the locator pin can be used on only one of two opposing reconfigurable pads, it may also be used on both. In addition to the location function described above, the pin may also serve as an over travel limit for a clamp arm, which prevents the SM-material from being deformed beyond its ability to recover.

[0031] The base member 12 can be constructed of any material onto which the reconfigurable pad 14 can be disposed, and which can withstand at least a portion of the weight of the workpiece 16. For example, the base member may be formed from a metal, alloy, ceramic, and the like.

[0032] The reconfigurable pad 14 comprises a shape memory material that is adapted to selectively conform to a surface contour of the workpiece 16 disposed thereon in response to an activation signal. Advantageously, the reconfigurable pad 14 can be restored to its original shape as may be desired as well as be reconfigured to accept a different workpiece 16 surface contour, thereby providing versatility to the fixture device 10 and overcoming the problems noted in the prior art. Optionally, the reconfigurable pad 14 may be thermally insulated from the tooling (i.e., base member 12) that it is mounted on and/or a training surface or work piece (e.g. 16) to avoid the quenching influence of any associated thermal mass. An alternative to insulating the reconfigurable pad 14 from the training surface (i.e., to which the reconfigurable pad 14 will conform) is to maintain the training surface at the training or conforming temperature (T_t) during the training (i.e., shape setting or conforming) step as will be described in greater detail below.

[0033] The reconfigurable pad 14 can be of any shape, form, or size, provided that it can selectively conform to the surface contour of the workpiece 16. For example, the reconfigurable pad may be a dense solid (e.g., box- or disc-shaped), perforated or porous, hollow (e.g., so as to form a chamber), granular, or the like.

[0034] Because the reconfigurable pad 14 can be adapted to substantially conform to any workpiece 16 surface contour, the fixture device 10 can be employed for a variety of different workpieces 16, thereby representing a significant commercial advantage in, for example, a flexible manufacturing system that traditionally employed multiple clamps and clamp/supporting member pads specific to individual workpieces 16. For example, significant savings can be obtained by reducing design, engineering, manufacturing, and purchasing of fixture devices for each product type (e.g., dissimilar body panels).

[0035] Shape memory materials generally refer to materials or compositions that have the ability to remember their original shape, which can subsequently be recalled by applying an external stimulus (i.e., an activation signal). As such, deformation of the shape memory material from the original shape can be a temporary condition, which can be used for fixturing a variety of workpieces 16 having different surface contours. Exemplary shape memory materials include shape memory alloys (SMAs), shape memory polymers (SMPs), shape memory ceramics (SMCs), baroplastics, composites of the foregoing shape memory materials with non-shape memory materials, and combinations comprising at least one of the foregoing shape memory materials. For convenience and by way of example, reference herein will be made to shape memory alloys and shape memory polymers. The shape memory ceramics, baroplastics, and the like can be employed in a similar manner as will be appreciated by those skilled in the art in view of this disclosure. For example, with baroplastic materials, a pressure induced mixing of nanophase domains of high and low glass transition temperature (T_g) components effects the shape change. Baroplastics can be processed at relatively low temperatures repeatedly without degradation. SMCs are similar to SMAs but can tolerate much higher operating temperatures than can other shape-memory materials. An example of an SMC is a piezoelectric material.

[0036] Shape memory alloys are alloy compositions with at least two different temperature-dependent phases. The most commonly utilized of these phases are the so-called martensite and austenite phases. In the following discussion, the martensite phase generally refers to the more deformable, lower temperature phase whereas the austenite phase generally refers to the more rigid, higher temperature phase. When

the shape memory alloy is in the martensite phase and is heated, it begins to change into the austenite phase. The temperature at which this phenomenon starts is often referred to as austenite start temperature (A_s). The temperature at which this phenomenon is complete is called the austenite finish temperature (A_f). When the shape memory alloy is in the austenite phase and is cooled, it begins to change into the martensite phase, and the temperature at which this phenomenon starts is referred to as the martensite start temperature (M_s). The temperature at which austenite finishes transforming to martensite is called the martensite finish temperature (M_f). It should be noted that the above-mentioned transition temperatures are functions of the stress experienced by the SMA sample. Specifically, these temperatures increase with increasing stress. In view of the foregoing properties, deformation of the shape memory alloy is preferably at or below the austenite transition temperature (at or below A_s). Subsequent heating above the austenite transition temperature causes the deformed shape memory material sample to revert back to its permanent shape. Thus, a suitable activation signal for use with shape memory alloys is a thermal activation signal having a magnitude that is sufficient to cause transformations between the martensite and austenite phases.

[0037] The temperature at which the shape memory alloy remembers its high temperature form when heated can be adjusted by slight changes in the composition of the alloy and through thermo-mechanical processing. In nickel-titanium shape memory alloys, for example, it can be changed from above about 100°C to below about -100°C. The shape recovery process can occur over a range of just a few degrees or exhibit a more gradual recovery. The start or finish of the transformation can be controlled to within a degree or two depending on the desired application and alloy composition. The mechanical properties of the shape memory alloy vary greatly over the temperature range spanning their transformation, typically providing shape memory effect, superelastic effect, and high damping capacity. For example, in the martensite phase a lower elastic modulus than in the austenite phase is observed. Shape memory alloys in the martensite phase can undergo large deformations by realigning the crystal structure arrangement with the applied stress, e.g., pressure from a matching pressure foot. As will be described in greater detail below, the material will retain this shape after the stress is removed.

[0038] Suitable shape memory alloy materials for fabricating the clamp/supporting member pad include, but are not intended to be limited to, nickel-titanium based alloys, indium-titanium based alloys, nickel-aluminum based alloys, nickel-gallium based alloys, copper based alloys (e.g., copper—zinc alloys, copper-aluminum alloys, copper-gold, and copper-tin alloys), gold-cadmium based alloys, silver-cadmium based alloys, indium-cadmium based alloys, manganese-copper based alloys, iron-platinum based alloys, iron-palladium based alloys, and the like. The alloys can be binary, ternary, or any higher order so long as the alloy composition exhibits a shape memory effect, e.g., change in shape, orientation, yield strength, flexural modulus, damping capacity, superelasticity, and/or similar properties. Selection of a suitable shape memory alloy composition depends on the temperature range where the component will operate.

[0039] Reference will now be made to a reconfigurable pad 14 formed of an SMA. To train/set the shape so as to accommodate the contour of the workpiece 16, the reconfigurable pad 14 is pressed against the workpiece 16 with a force (F_1) that causes the stresses in the reconfigurable pad 14 to exceed the first yield point of the martensite phase. It should be understood that training or setting the shape of the reconfigurable pad can be done using a so-called “master” article with a shape substantially similar to the workpiece. This master article may be a programmable device that can generate many different surface contours (e.g. a bed-of-nails, wherein the position of each of the nails is programmable).

[0040] The SMA can be in the form of a foam or other structure as may be desired for the particular application, e.g., springs, bands, laminates, and the like, and is not intended to be limited to any particular form or shape. The SMA in the martensite phase undergoes a large, seemingly plastic deformation, at a nearly constant stress. This allows the reconfigurable pad 14 to deform freely in order to conform to the contours of the workpiece 16, as shown in Figure 2. When the training force (i.e., setting force) is removed, the reconfigurable pad 14 will retain most, if not all, of the deformation produced during the training step, as illustrated in Figure 3. A small part of the induced deformation may be lost due to elastic recovery.

[0041] Although reference has been made to a reconfigurable pad 14 formed of an SMA in the martensite phase, it should be understood that training could occur with a reconfigurable pad 14 formed of the SMA in the austenite phase. In this manner, the SMA behaves similar to a high stiffness rubber-like material. The SMA plastically deforms during the training step as a result of a stress-induced austenite to martensite transformation so as to conform to the workpiece 16 surface. However, unlike the martensitic SMA described in the previous paragraph, the austenitic SMA reconfigurable pad 14 does not retain the deformation induced in it after the training force is removed. Hence, this reconfigurable pad 14 has to be trained for each workpiece 16 of a different shape.

[0042] One or more fixture devices 10 with a contoured (i.e., trained) reconfigurable pad 14 are then used to fixture the workpiece 16 in a manner that distributes the reaction force over a large area, and thus, minimizes the possibility of damaging the surface of the workpiece 16. The fixturing force (F_2), which is either a support force or a clamp force, during regular use of the reconfigurable pad(s) 14 should, generally, be smaller than F_1 such that the stresses induced by F_2 do not exceed the first yield point of the martensite phase. Fixturing forces during regular use that are significantly higher than the training forces are also possible if the training step is continued to a point where the stress in the reconfigurable pad(s) 14 increases beyond the first yield point but not beyond the second yield point of the martensite phase SMA. However, it should be noted that the latter approach requires closer control, both during the training step and during regular use to ensure that the conformity between the reconfigurable pad(s) 14 and the support surface on the workpiece 16 is not compromised.

[0043] The reconfigurable pad 14 might optionally undergo a reset step before they are reconfigured for fixturing a workpiece 16 at a location with a different surface geometry. In the reset step, the reconfigurable pad 14 is unloaded and heated to a temperature above the austenite-finish temperature of the SMA, and cooled back to the ambient or working temperature as desired. Heating the reconfigurable pad 14 to a temperature above the austenite finish temperature produces a martensite to austenite phase transformation that is accompanied by complete recovery of the seemingly plastic deformation induced during the training step (see Figure 4)

provided that the reconfigurable pad 14 is unloaded, the recovery is not constrained in any manner and sufficient time is allowed for the process. This recovery restores the reconfigurable pad 14 to its original (i.e., undeformed) configuration, which is retained even after it has been cooled. The training process is then repeated for the new workpiece 16 surface geometry. Alternatively, the reconfigurable pad 14 can be trained for the new surface contour directly as opposed to resetting to the original shape(s).

[0044] As previously mentioned, other suitable shape memory materials for use in the reconfigurable pad 14 are shape memory polymers (SMPs). "Shape memory polymer" generally refers to a polymeric material, which exhibits a change in a property, such as an elastic modulus, a shape, a dimension, a shape orientation, or a combination comprising at least one of the foregoing properties upon application of an activation signal. Shape memory polymers may be thermoresponsive (i.e., the change in the property is caused by a thermal activation signal), photoresponsive (i.e., the change in the property is caused by a light-based activation signal), moisture-responsive (i.e., the change in the property is caused by a liquid activation signal such as humidity, water vapor, or water), or a combination comprising at least one of the foregoing.

[0045] Generally, SMPs are phase segregated co-polymers comprising at least two different units, which may be described as defining different segments within the SMP, each segment contributing differently to the overall properties of the SMP. As used herein, the term "segment" refers to a block, graft, or sequence of the same or similar monomer or oligomer units, which are copolymerized to form the SMP. Each segment may be crystalline or amorphous and will have a corresponding melting point or glass transition temperature (T_g), respectively. The term "thermal transition temperature" is used herein for convenience to generically refer to either a T_g or a melting point depending on whether the segment is an amorphous segment or a crystalline segment. For SMPs comprising (n) segments, the SMP is said to have a hard segment and (n-1) soft segments, wherein the hard segment has a higher thermal transition temperature than any soft segment. Thus, the SMP has (n) thermal transition temperatures. The thermal transition temperature of the hard segment is termed the "last transition temperature", and the lowest thermal transition temperature

of the so-called “softest” segment is termed the “first transition temperature”. It is important to note that if the SMP has multiple segments characterized by the same thermal transition temperature, which is also the last transition temperature, then the SMP is said to have multiple hard segments.

[0046] When the SMP is heated above the last transition temperature, the SMP material can be imparted a permanent shape. A permanent shape for the SMP can be set or memorized by subsequently cooling the SMP below that temperature. As used herein, the terms “original shape”, “previously defined shape”, and “permanent shape” are synonymous and are intended to be used interchangeably. A temporary shape can be set by heating the material to a temperature higher than a thermal transition temperature of any soft segment yet below the last transition temperature, applying an external stress or load to deform the SMP, and then cooling below the particular thermal transition temperature of the soft segment while maintaining the deforming external stress or load.

[0047] The permanent shape can be recovered by heating the material, with the stress or load removed, above the particular thermal transition temperature of the soft segment yet below the last transition temperature. Thus, it should be clear that by combining multiple soft segments it is possible to demonstrate multiple temporary shapes and with multiple hard segments it may be possible to demonstrate multiple permanent shapes. Similarly using a layered or composite approach, a combination of multiple SMPs will demonstrate transitions between multiple temporary and permanent shapes.

[0048] For SMPs with only two segments, the temporary shape of the shape memory polymer is set at the first transition temperature, followed by cooling of the SMP, while under load, to lock in the temporary shape. The temporary shape is maintained as long as the SMP remains below the first transition temperature. The permanent shape is regained when the SMP is once again brought above the first transition temperature with the load removed. Repeating the heating, shaping, and cooling steps can repeatedly reset the temporary shape.

[0049] Most SMPs exhibit a “one-way” effect, wherein the SMP exhibits one permanent shape. Upon heating the shape memory polymer above a soft segment thermal transition temperature without a stress or load, the permanent shape is achieved and the shape will not revert back to the temporary shape without the use of outside forces.

[0050] As an alternative, some shape memory polymer compositions can be prepared to exhibit a “two-way” effect, wherein the SMP exhibits two permanent shapes. These systems include at least two polymer components. For example, one component could be a first cross-linked polymer while the other component is a different cross-linked polymer. The components are combined by layer techniques, or are interpenetrating networks, wherein the two polymer components are cross-linked but not to each other. By changing the temperature, the shape memory polymer changes its shape in the direction of a first permanent shape or a second permanent shape. Each of the permanent shapes belongs to one component of the SMP. The temperature dependence of the overall shape is caused by the fact that the mechanical properties of one component (“component A”) are almost independent of the temperature in the temperature interval of interest. The mechanical properties of the other component (“component B”) are temperature dependent in the temperature interval of interest. In one embodiment, component B becomes stronger at low temperatures compared to component A, while component A is stronger at high temperatures and determines the actual shape. A two-way memory device can be prepared by setting the permanent shape of component A (“first permanent shape”), deforming the device into the permanent shape of component B (“second permanent shape”), and fixing the permanent shape of component B while applying a stress.

[0051] It should be recognized by one of ordinary skill in the art that it is possible to configure SMPs in many different forms and shapes. Engineering the composition and structure of the polymer itself can allow for the choice of a particular temperature for a desired application. For example, depending on the particular application, the last transition temperature may be about 0°C to about 300°C or above. A temperature for shape recovery (i.e., a soft segment thermal transition temperature) may be greater than or equal to about -30°C. Another temperature for shape recovery may be greater than or equal to about 40°C. Another temperature for shape recovery

may be greater than or equal to about 100°C. Another temperature for shape recovery may be less than or equal to about 250°C. Yet another temperature for shape recovery may be less than or equal to about 200°C. Finally, another temperature for shape recovery may be less than or equal to about 150°C.

[0052] Optionally, the SMP can be selected to provide stress-induced yielding, which may be used directly (i.e. without heating the SMP above its thermal transition temperature to 'soften' it) to make the pad conform to a given surface. The maximum strain that the SMP can withstand in this case can, in some embodiments, be comparable to the case when the SMP is deformed above its thermal transition temperature.

[0053] Although reference has been, and will further be, made to thermoresponsive SMPs, those skilled in the art in view of this disclosure will recognize that photoresponsive, moisture-responsive SMPs and SMPs activated by other methods may readily be used in addition to or substituted in place of thermoresponsive SMPs. For example, instead of using heat, a temporary shape may be set in a photoresponsive SMP by irradiating the photoresponsive SMP with light of a specific wavelength (while under load) effective to form specific crosslinks and then discontinuing the irradiation while still under load. To return to the original shape, the photoresponsive SMP may be irradiated with light of the same or a different specific wavelength (with the load removed) effective to cleave the specific crosslinks. Similarly, a temporary shape can be set in a moisture-responsive SMP by exposing specific functional groups or moieties to moisture (e.g., humidity, water, water vapor, or the like) effective to absorb a specific amount of moisture, applying a load or stress to the moisture-responsive SMP, and then removing the specific amount of moisture while still under load. To return to the original shape, the moisture-responsive SMP may be exposed to moisture (with the load removed).

[0054] Suitable shape memory polymers, regardless of the particular type of SMP, can be thermoplastics, thermosets-thermoplastic copolymers, interpenetrating networks, semi-interpenetrating networks, or mixed networks. The SMP "units" or "segments" can be a single polymer or a blend of polymers. The polymers can be linear or branched elastomers with side chains or dendritic structural elements.

Suitable polymer components to form a shape memory polymer include, but are not limited to, polyphosphazenes, poly(vinyl alcohols), polyamides, polyimides, polyester amides, poly(amino acid)s, polyanhydrides, polycarbonates, polyacrylates, polyalkylenes, polyacrylamides, polyalkylene glycols, polyalkylene oxides, polyalkylene terephthalates, polyortho esters, polyvinyl ethers, polyvinyl esters, polyvinyl halides, polyesters, polylactides, polyglycolides, polysiloxanes, polyurethanes, polyethers, polyether amides, polyether esters, and copolymers thereof. Examples of suitable polyacrylates include poly(methyl methacrylate), poly(ethyl methacrylate), poly(butyl methacrylate), poly(isobutyl methacrylate), poly(hexyl methacrylate), poly(isodecyl methacrylate), poly(lauryl methacrylate), poly(phenyl methacrylate), poly(methyl acrylate), poly(isopropyl acrylate), poly(isobutyl acrylate) and poly(octadecylacrylate). Examples of other suitable polymers include polystyrene, polypropylene, polyvinyl phenol, polyvinylpyrrolidone, chlorinated polybutylene, poly(octadecyl vinyl ether), poly(ethylene vinyl acetate), polyethylene, poly(ethylene oxide)-poly(ethylene terephthalate), polyethylene/nylon (graft copolymer), polycaprolactones-polyamide (block copolymer), poly(caprolactone) diethacrylate-n-butyl acrylate, poly(norbornyl-polyhedral oligomeric silsequioxane), polyvinylchloride, urethane/butadiene copolymers, polyurethane-containing block copolymers, styrene-butadiene block copolymers, and the like. The polymer(s) used to form the various segments in the SMPs described above are either commercially available or can be synthesized using routine chemistry. Those of skill in the art can readily prepare the polymers using known chemistry and processing techniques without undue experimentation.

[0055] As will be appreciated by those skilled in the art, conducting polymerization of different segments using a blowing agent can form a shape memory polymer foam, for example, as may be desired for some applications. The blowing agent can be of the decomposition type (evolves a gas upon chemical decomposition) or an evaporation type (which vaporizes without chemical reaction). Exemplary blowing agents of the decomposition type include, but are not intended to be limited to, sodium bicarbonate, azide compounds, ammonium carbonate, ammonium nitrite, light metals which evolve hydrogen upon reaction with water, azodicarbonamide,

N, N' dinitrosopentamethylenetetramine, and the like. Exemplary blowing agents of the evaporation type include, but are not intended to be limited to, trichloromonofluoromethane, trichlorotrifluoroethane, methylene chloride, compressed nitrogen, and the like.

[0056] Reference will now be made to reconfigurable pads 14 formed of a thermoresponsive SMP, which can take any form (e.g., foam, laminate, solid, composite, and the like). The reconfigurable pad 14 made of the SMP is in its stiff, glassy form at the operating temperatures of the fixture device 10, which is below the lowest thermal transition temperature of the SMP. In the training step, the reconfigurable pad 14 is heated to a temperature above the thermal transition temperature, which causes the SMP to transition to a polymeric form having lower stiffness (i.e., decreased flexural modulus properties). The reconfigurable pad 14 is then pressed against the workpiece 16 with a force (F_1) and made to deform such that it sufficiently conforms to the contoured surface of the workpiece 16, as shown in Figures 2 and 6.

[0057] The reconfigurable pad 14 is then cooled below the thermal transition temperature, while still under load (i.e., while holding the configuration attained at the end of the previous step) to bring the SMP back to its stiff glassy form. As illustrated in Figures 3 and 7, the reconfigurable pad 14 retains the configuration 'taught' during the training step even after it has cooled down to the regular working temperature and is suitable for use to fixture additional workpieces 16. As the stiffness of the SMP reconfigurable pad 14 is higher when the SMP is in its glassy form than when it is in its soft, polymeric form, the clamping force resisted by the reconfigurable pad 14 can be greater than the training force.

[0058] After a fixturing (i.e., supporting and/or clamping) task is completed, the reconfigurable pad 14 can be reheated to a temperature above the thermal transition temperature and pressed against a workpiece 16 for the next task so long as the workpieces have similar surface contours, i.e., the reconfigurable pad(s) 14 can proceed directly to the training step shown in Figures 2 and 6. However, in some cases it may be necessary to reset the reconfigurable pad 14 to its original configuration followed by a training step before it can be used to support a workpiece

16 at a location with a different surface geometry. In the optional reset step, the reconfigurable pad 14 is unloaded and heated to above the thermal transition temperature. The reconfigurable pad 14 is held unloaded at that temperature (i.e., with the SMP in the soft, polymeric form), until the reconfigurable pad 14 has regained its original configuration. Since the SMP reconfigurable pad 14 will have a low stiffness, shape recovery may be assisted by external means such as by reorienting the reconfigurable pad 14 to use gravity loading. Other means of shape recovery assistance can include the use of compressed air, immersion in a fluid, use of another material which opposes the SMP within a composite (as will be described below), and the like. When the shape recovery is complete and/or substantially complete, the reconfigurable pad 14 is trained for a new fixturing task.

[0059] Composites of a shape memory material and an additional material can also be employed in the reconfigurable pad 14. As stated above, the composite is not intended to be limited to any specific combination of materials. The additional material may be a non-shape memory material and/or an additional shape memory material. The additional shape memory material may be of the same class (e.g., different shape memory polymers), or a different class (e.g. a shape memory polymer and a shape memory alloy).

[0060] In one embodiment, if the composite comprises a shape memory polymer and a non-shape memory metal or metal alloy, the non-shape memory material can be configured to provide an assist mechanism to an SMP to facilitate shape change. As an example, such a composite-containing reconfigurable pad 14 may comprise an element 18 distributed within an SMP matrix 20. The element 18 is depicted as a spring in Figure 5, but may take any shape (e.g., strip, mesh, honeycomb, and the like). The element 18 provides a return mechanism for restoring the reconfigurable pad 14 to its original shape or to the shape of a load under which the reconfigurable pad 14 is placed.

[0061] Optionally, if electrically conducting materials form the element 18, these materials can also be used for resistive or inductive heating to effect the phase transformation of the SMP itself.

[0062] Optionally, element 18 can be formed of a shape memory material (e.g., an SMA) so as to enable more functionality in the composite. By way of example, SMA materials can be selected to be electrically conducting and have an elastic modulus greater than that of the SMP in both its soft and hard forms. Although other common metals, such as steel and aluminum, also possess these properties, these materials have fully recoverable strains that are smaller than those for SMA materials (e.g., less than about 1% for most metals versus about 8% for some SMA materials). Therefore, a reconfigurable pad 14 made from an SMA-SMP composite can undergo larger fully recoverable deformations than a reconfigurable pad 14 made from an SMP composite reinforced with other metals, provided that the reinforcing component is of the same configuration in both cases. As a consequence, an SMA-SMP composite reconfigurable pad 14 can be configured for a wider variety of fixturing tasks than a composite reconfigurable pad 14 made of SMP and a material with a smaller fully recoverable strain than an SMA (e.g., steel, aluminum, and like non-shape memory materials). Despite the advantages of using SMA over other metals as the second phase in an SMP-based composite, it may be desirable to employ other metals to reduce costs, for example.

[0063] In one embodiment, composite reconfigurable pad 14 comprises SMA material distributed throughout a matrix 20 made from the SMP material. The SMA is in close physical (e.g. mechanical and thermal) contact with the surrounding SMP matrix 20.

[0064] As an illustrative example, the compositions of the SMA and SMP constituents of the composite can be chosen such that the various characteristic temperatures for these materials are related by: $T_w < T_{g1} < T_t < A_s < A_f < T_r < M_d$, T_{max} , wherein T_w is the environmental temperature in which the fixture device 10 is disposed and operated; T_{g1} is the first thermal transition temperature of the SMP; T_t is the temperature employed for training (setting is done by cooling to below T_{g1}) of the deformed shape; A_s is the austenite start temperature; A_f is the austenite finish temperature; T_r is the temperature employed for recovery of the deformation in the configurable pad 14 to its original shape; M_d is the temperature above which the SMA loses its shape memory properties; and T_{max} is the lesser of the last transition temperature or the oxidation temperature for the SMP material. Consequently, the

SMA is in its stress-free martensite phase and the SMP is in its stiff, glassy form at the regular working or operating temperature of the reconfigurable pad 14. Other SMA and SMP compositions could also be used where, for example, the above temperature relationships do not hold. The relationship described above is used in the description that follows, but is by no means intended to be limiting.

[0065] In the training step, the reconfigurable pad 14 can be resistively heated by passing current through the SMA element 18. The heating is controlled to raise the temperature of the SMA and the surrounding SMP to T_t , which is above T_{g1} . The SMA continues to be in the martensite phase as T_t is also lower than A_s , at which the martensite to austenite phase transformation is initiated in the SMA. At this stage, the SMP is in its soft, polymeric form and the SMA is still in its lower stiffness martensite phase. The reconfigurable pad 14 is then contacted with the workpiece 16 in order to deform it to conform to the workpiece 16. The SMA also deforms along with the SMP, and depending on the level of stress developed in the SMA, it can undergo either elastic deformation (e.g., less than or equal to about 1% strain) alone or elastic deformation in combination with pseudo-plastic deformation (e.g., up to about 8% strain).

[0066] After the reconfigurable pad 14 has achieved sufficient conformance with the workpiece 16, the setting step is initiated. In this step, the current passing through the SMA is switched off and the reconfigurable pad 14 is allowed to cool down to T_w , while holding the shape 'taught' during the training step. External cooling may also be used to accelerate this step. As the SMP increases its elastic modulus upon cooling, the SMA has elastic, and possibly pseudo-plastic, strain locked into it. The SMA element 18 within the SMP matrix 20 is chosen such that, for example, the stiffness of its structural form is smaller than that of the SMP matrix 20, while in its stiff glassy form. This ensures that the elastic part of the strain locked into the SMA element 18 does not distort the 'taught' shape to any significant extent. Therefore, the reconfigurable pad 14 retains this 'taught' shape after the setting process is over and the training forces are removed. Maintaining the relative positions of the reconfigurable pad 14 and the workpiece 16 throughout the process can ensure the holding of the trained shape during the setting process. Alternatively, a constant training force, which depends on the response of the reconfigurable pad 14 during the

setting process, may be used such that the final shape achieved is the desired one, e.g. the constant force used in the training and setting steps may yield a surface contour that is different from the desired one, but the change in the elastic response of the composite pad, as it is cooled below T_{g1} , causes the desired final surface to be produced in the pad at T_w . This is conceptually similar to the over-bending done on pressed sheet metal parts to compensate for the change in part geometry due to elastic 'springback'.

[0067] When the reconfigurable pad 14 is to be reconfigured for fixturing a workpiece having a different surface contour, it is unloaded and the temperature increased to T_t . During this process, the SMP transitions from its stiff, glassy form to a soft, polymeric form, thereby releasing the elastic strain locked into the SMA during the training and setting steps. The elastic recovery force provided by the SMA assists the SMP in reverting to its original configuration. The reconfigurable pad 14 can then be trained for the new workpiece 16. Complete recovery of the original configuration may not be necessary in some cases, and the reconfigurable pad 14 can be trained for the new workpiece 16 immediately after it has been heated to T_t .

[0068] If the SMA has undergone any pseudo-plastic strain during the training/setting steps and/or the reconfigurable pad 14 needs to be restored to the original configuration before training it for a new workpiece 16, the heating of the unloaded reconfigurable pad 14 is continued until the reset temperature is attained, which is chosen to be greater than A_f , which is greater than T_{g1} . Heating the SMA above A_f causes the martensite phase to transition to the austenite phase. This phase transition is accompanied by a recovery of the pseudo-plastic strain. Hence, the SMA reverts to its strain-free original configuration. In some embodiments, there may be some un-recovered strain as the number of cycles increases. A significant recovery stress is produced in the SMA during this strain recovery. This stress assists the SMP in recovering its original configuration. When the shape recovery is sufficiently complete, the current flowing through any or all SMA elements 18 is adjusted to a level that brings the temperature of the reconfigurable pad 14 to T_t . The reconfigurable pad can now be trained for the next workpiece 16.

[0069] Optionally, if the SMA is sheathed in a thermally insulating cover, but continues to be in close mechanical contact with the SMP, the shape memory effect can still be used to aid in the shape recovery of the reconfigurable pad 14 during the reset step. The only deviation from the procedure described above would be that current is not passed through the SMA elements for heating. A different heat source would be used during the training and reset steps. This results in a less complex temperature relationship ($T_w < T_{g1} < T_t \leq T_r < T_{max}$), which translates into greater freedom in choosing the SMA and SMP components.

[0070] In another embodiment, the SMA can be used for resistive heating and super-elastic reset. In this embodiment, the super-elastic behavior of the SMA component is used to allow the reconfigurable pad 14 to undergo large deformations during the training step, which are fully recoverable during the reset step. The elastic recovery forces exerted by the super-elastic SMA component help the reconfigurable pad 14 to recover its original configuration when it needs to be reconfigured for supporting a workpiece 16 at a location with a different surface geometry.

[0071] In one embodiment, the reconfigurable pad 14 can comprise an SMA element 18 in the austenite phase distributed within an SMP material. The SMP material is in its stiff, glassy form at the regular working temperature. The SMA and SMP are in close physical (i.e., mechanical, thermal, and the like) contact; the compositions of which are chosen such that their characteristic temperatures are related in the following relationship: $A_f < T_w < T_{g1} < T_t \leq T_r < M_d, T_{max}$.

[0072] In the training step, the reconfigurable pad 14 is heated to T_t , where the SMP transforms into its soft, polymeric form while the SMA remains in its austenite phase. The reconfigurable pad 14 is then pressed against the workpiece 16 and deformed to make it conform to the surface contour particular to the workpiece 16. The soft, polymeric SMP deforms easily and can undergo large strains (e.g. up to 200 %). Initially, the SMA deforms elastically, but later if the stress in the SMA material exceeds a critical stress (σ_m), the SMA undergoes a pseudo-plastic deformation. The SMA can undergo large recoverable strains (e.g., up to about 8 %) at nearly constant stress during the pseudo-plastic deformation, which is associated

with a stress-induced austenite to martensite phase transformation in the SMA material.

[0073] After the desired conformity between the reconfigurable pad 14 and the workpiece 16 is achieved, the reconfigurable pad 14 is allowed to cool down to T_w , while holding the shape 'taught' during the training step. Other cooling methods (e.g., air jet) may be used to assist and/or accelerate the cooling process as desired. When the temperature drops below T_{g1} , the SMP transforms into its stiff, glassy form, thereby locking the strain (elastic and, possibly, pseudo-plastic) in the SMA. As discussed earlier, the SMA element 18 within the SMP matrix 20 can be chosen such that its stiffness is smaller than that of the SMP matrix 20 in its stiff glassy form. Consequently, the reconfigurable pad 14 retains the 'taught' shape at T_w and is ready for use.

[0074] When the reconfigurable pad 14 needs to be reconfigured to support another surface, it is unloaded and heated to T_r , which is above T_{g1} . As the elastic modulus of the SMP decreases, the elastic and pseudo-plastic strain locked into the SMA is gradually recovered. The SMA exerts elastic restoring forces on the surrounding SMP that can assist the SMP in recovering its original configuration. It should be noted that recovery of the original configuration is optional and, in some embodiments, the reconfigurable pad 14 can be directly taken to the training step for the next workpiece 16 after it has been heated to T_r .

[0075] In yet another embodiment, the SMA can be adapted for heating, actuation, and reset. In this embodiment, at the regular working or operating temperature, the reconfigurable pad 14 comprises pseudo-plastically strained SMA material in the martensite phase distributed within a stiff, glassy SMP matrix. The SMA and SMP components of the reconfigurable pad 14 are in close physical contact (e.g. mechanical, thermal, and the like) and their composition is chosen such that the characteristic temperatures are related as follows: $T_w < T_{g1}$, $M_f < T_t \leq T_r < A_s < T_a$, $A_f < T_{max}$, M_d . In this embodiment, the composite includes at least two different SMA elements 18 and 22, shown in Figure 5, wherein SMA element 18 is selected to be antagonistic to SMA element 22. That is, SMA element 18, on actuation, will seek to

deform the SMP matrix 20 in a direction opposite to that of the element 22. SMA elements 18 and 22 are distributed throughout the SMP matrix 20.

[0076] In the training step, the reconfigurable pad 14 is heated to T_t , which is greater than T_{g1} . As a consequence, the SMP transitions to its soft, polymeric form. However, the SMA remains in the martensite phase because T_t is lower than A_s , at which the martensite to austenite phase transition is initiated in the SMA. A subset of the SMA elements 18 and/or 22 in the reconfigurable pad 14 is selectively actuated by heating the subset such that these elements are heated to their actuation temperature. Heating the selected subset of the pre-strained martensite phase SMA elements above A_s initiates the martensite to austenite phase transition in these elements. As a consequence of this transformation, the activated SMA elements 18 and/or 22 attempt to revert to their strain-free configuration and, in this process, exert force on the surrounding SMP matrix 20 and other SMA elements 18 and/or 22. Note that the strain-free configuration for the SMA elements is not the same as the configuration of these elements in the original configuration of the reconfigurable pad 14 because the SMA elements are pre-strained in the latter configuration. The elements 18 and/or 22 forming the actuated subset are chosen such that, as a consequence of actuating this subset, the reconfigurable pad 14 deforms into a geometry that is suitable for fixturing the given workpiece 16.

[0077] While it may be desirable to achieve the required geometry entirely by using SMA actuation, an assist can also be provided to fine tune the desired final geometry. For example, a further mechanical step, in which the partially trained reconfigurable pad 14 is pressed against a training surface at a temperature above T_{g1} , may be used. This is especially desirable if close tolerances are desired on the contoured surface. The work required in the mechanical training step is less in this case than if the entire deformation of the reconfigurable pad 14 was to be done by pressing the reconfigurable pad 14 against the training surface. As the SMP material is in its soft, polymeric form, the actuation force obtained from the SMA elements can easily deform it. The non-actuated SMA elements, which are in the martensite phase, undergo pure elastic deformation initially, but can deform pseudo-plastically if the stress in these elements exceeds the first yield stress of the martensite phase. The elastic deformation is limited to small fully recoverable strains (e.g., less than about

1%), but the pseudo-plastic deformation can accommodate much larger fully recoverable strains (e.g., up to about 8%).

[0078] After the reconfigurable pad 14 conforms sufficiently to the training surface (e.g., workpiece 16), it is cooled to T_w while holding the configuration attained at the end of the training step. This is achieved for example by switching off a current passing through only those SMA elements that are not actuated in the training step. Other cooling means may also be used to assist and/or accelerate this process. The actuation current passing through the actuated SMA elements may be adjusted in keeping with the changing modulus of the SMP matrix such that the surface contour 'taught' during the training step is reasonably unchanged until the bulk of the SMP material has transformed back to its stiff, glassy form. The actuation current is then switched off and the actuated elements are cooled down to T_w . The 'taught' shape is held during the secondary mechanical training step, if used, by maintaining the relative position of the training surface until the SMP has glassified. Other alternatives discussed earlier to hold the 'taught' shape during the setting step can also be used. At the end of the setting process, the reconfigurable pad 14 retains the shape 'taught' during the training step and is ready for use. In this condition, the SMA elements (actuated or not) have some elastic, and possibly some pseudo-plastic strain.

[0079] When the reconfigurable pad 14 needs to be reconfigured for another workpiece 16, it can be heated to T_r . During this process, the SMP material transforms into its soft, polymeric form as T_r is greater than T_{g1} . The elastic strain locked in the SMA elements (actuated or not) is gradually released during the softening of the SMP. The accompanying elastic recovery forces help in restoring the reconfigurable pad 14 to the original configuration. If complete recovery of the original shape is not desired, the heated reconfigurable pad 14 can be directly trained for the next workpiece 16.

[0080] In the event that the shape recovery obtained in the above process is insufficient for the reconfigurable pad 14 to be trained for a new workpiece 16, the shape recovery process can be continued. If any SMA elements have undergone pseudo-plastic deformation during the training/setting steps, that strain cannot be

recovered by heating the reconfigurable pad 14 to T_r . In this case, the set of SMA elements (20 or 22), which are antagonistic to those actuated in the training step, is actuated while the reconfigurable pad 14 is held at T_r . The actuation force exerted on the reconfigurable pad 14 by these elements (20 or 22), as they undergo the martensite to austenite phase transition helps the reconfigurable pad 14 recover its original configuration. After the shape recovery is sufficiently complete, the reconfigurable pad 14 can be trained for the next workpiece 14.

[0081] In yet another embodiment, the SMA can be adapted to provide heating, actuation and reset by means of a two-way shape memory effect. In this embodiment (see Figure 5), at the working temperature, the reconfigurable pad 14 comprises SMA element 18 distributed within the stiff, glassy SMP matrix 20. The SMA material is in the martensite phase and has been processed to allow the SMA element 18 to 'remember' two shapes: a high temperature shape, which is the natural shape of the element when the SMA is fully austenitic; and a low temperature shape, which is the natural shape when the material is fully martensitic. The SMA and SMP materials are in close physical (e.g., mechanical, thermal) contact and their composition is chosen such that the characteristic temperatures are related as follows: $T_w < M_f < M_s < T_{g1} < T_t \leq T_r < A_s < T_a \leq A_f < T_{max}, M_d$.

[0082] In the training step, the reconfigurable pad 14 is heated to T_t , which is greater than T_{g1} . As a consequence, the SMP transitions to its soft, polymeric form. The reconfigurable pad 14 can be heated, for example, by passing current through all of the SMA elements 18. Other heating methods may also be used to assist and/or accelerate the heating process. A subset of the SMA elements 18 in the reconfigurable pad 14 can then be actuated by heating them to the appropriate actuation temperature. This selective actuation can be obtained, for example, by increasing the current passing through those elements 18. Heating the martensite phase SMA elements 18 to a temperature above A_s initiates a martensite to austenite phase transition in those elements 18. As a consequence of this transformation, the actuated SMA elements 18 try to attain their high temperature shape, and in the process exert force on the surrounding SMP matrix 20 and other SMA elements 18. The elements 18 forming the actuated set are chosen such that actuating this set

deforms the reconfigurable pad 14 into a geometry that is suitable for the given workpiece 16.

[0083] While it is desirable to achieve the required geometry entirely by using SMA actuation, it is only necessary that the actuation achieve a geometry that is in the neighborhood of the desired one. A further mechanical step, in which the partially trained reconfigurable pad 14 is pressed against a training surface at a temperature above T_{g1} , may be used to obtain the geometry necessary for the given workpiece 16. The work required in the mechanical step is less in this case than if the entire deformation of the pad were to be done by pressing the reconfigurable pad 14 against the training surface. As the SMP material is in its soft, polymeric form, the actuation force obtained from the SMA elements 18 can easily deform it. The non-actuated SMA elements 18 remain in the martensite phase throughout the training process and undergo purely elastic deformation initially, but can deform pseudo-plastically if the stress in these elements 18 exceeds the first yield stress of the martensite phase. The elastic deformation is limited to small fully recoverable strains (e.g., less than about 1%), but the pseudo-plastic deformation can accommodate larger fully recoverable strains (e.g., up to about 2%).

[0084] After the reconfigurable pad 14 conforms sufficiently to the training surface with the desired geometry, it is cooled to T_w , while holding the configuration attained at the end of the training step. This is achieved, for example, by switching off the current passing through only those SMA elements 18 that are not actuated in the training step. As in the various other embodiments, alternative cooling means may also be used to assist and/or accelerate this process. The actuation current passing through the actuated SMA elements 18 is adjusted to prevent or minimize the deviation of the surface from the 'taught' shape until the bulk of the SMP material has transformed back to its stiff, glassy form. This may result in the temperature of these elements 18 remaining above A_f , and hence the actuated elements 18 continue to strive to attain their high temperature shape, while the bulk of the SMP matrix 20 is glassifying. The actuation current is then switched off and the actuated elements 18 are cooled down to T_w . The 'taught' shape is held by keeping the elements 18 actuated, and if a secondary mechanical training step is used, by keeping the reconfigurable pad 14 pressed against the training surface until the SMP has

glassified. When the temperature of the actuated SMA elements 18 drops below the martensite-start temperature (M_s) during the cooling process, the austenite in the SMA begins to transform to martensite. This transformation is accompanied by these elements attempting to revert back to their low temperature shape. However, as $M_s < T_{g1}$, the surrounding SMP matrix 20 has glassified before the austenite to martensite phase transformation and the associated shape change can take effect. Consequently, the reconfigurable pad 14 retains the shape 'taught' during the training step at the conclusion of the setting process and is ready for use. In this condition, the SMA elements 18 (actuated or not) have some elastic, and possibly some pseudo-plastic, strain locked therein.

[0085] When the reconfigurable pad 14 needs to be reconfigured for supporting a workpiece 16 at a location with a different surface geometry, the pad can be heated to the T_r by passing current through all of the SMA elements 18, for example. As T_r is greater than T_{g1} , the SMP material transforms into its soft, polymeric form. The elastic strain locked in the SMA elements (actuated or not) is gradually released during the softening of the SMP. The accompanying elastic recovery forces help in restoring the pad to its original configuration.

[0086] As described above, complete recovery of the original shape is not necessary, and the heated reconfigurable pad 14 can be trained for the next fixturing task after the SMP matrix 20 has softened sufficiently. In the event that the shape recovery obtained in the above process is insufficient, the shape recovery process needs to be continued. If any SMA elements 18 have undergone pseudo-plastic deformation during the training and setting steps, that strain cannot be recovered by simply heating the reconfigurable pad 14 to T_r . In this case, the SMA elements 18 that have undergone pseudo-plastic deformation are heated to the actuation temperature (e.g., by increasing the current passing through these elements), while the rest of the reconfigurable pad 14 is held at about T_r . In doing this, the elements 18 are able to undergo the martensite to austenite phase transition, and their temperature can subsequently be reduced to T_r . The reconfigurable pad 14 is now ready to be reconfigured for the next fixturing task.

[0087] Although reference has been made to using an electric current to heat the shape memory material of the reconfigurable pad 14 of the fixture device 10, various other methods can be employed to effect the temperature changes used for the various phase transformations described above. For example, heating of the reconfigurable pad 14 can be effected by dipping or exposing it or the entire fixture device 10 to heated fluids (liquids and/or gasses); by inductive heating when electrically conductive materials are employed; by exposing it to incident laser light; by thermoelectric heating; by microwave heating; by infrared heating; by flash lamps; and the like. In a similar manner, various means of cooling the reconfigurable pad 14 include, but are not intended to be limited to, dipping or exposing the reconfigurable pad 14 or the entire fixture device 10 to cooled fluids; thermoelectric cooling; and the like.

[0088] Alternatively, to increase heating and cooling transfer efficiency two fixture devices 10 can be employed, wherein one fixture device 10 is in a so-called “stand-by” mode (or trained for a second workpiece 16) and the other is employed for a given workpiece 16. Still further, different types of SMA elements 18 and/or 22 can be employed wherein one subset of elements 18 (or 22) has a different phase transformation temperature than the other subset of elements 22 (or 18).

[0089] Reference will now be made to use of a thermoelectric device (i.e., as the activation device generally designated 24) for heating and/or cooling the reconfigurable pad 14 of the fixture device 10. A thermoelectric device is a solid-state electronic component that can emit or absorb heat upon the passage of a current across the device, or vice versa. To generate heat differences, a thermoelectric device relies on the Peltier effect, which occurs when a current is passed through a pair of dissimilar conductors connected in a closed loop. The current drives a transfer of heat from one junction of the two dissimilar conductors to the other. The conductors, which can be semiconductors, metals, ionic conductors, or the like, attempt to return to the charge equilibrium that existed before the current was applied by absorbing energy at one junction and releasing it at the other (i.e., one junction cools off while the other heats up). Additional couples (pairs of dissimilar conductors) can be connected in series to enhance this effect. The direction of heat transfer is controlled

by the polarity of the current, (i.e., reversing the polarity will change the direction of transfer and thus whether heat is absorbed or emitted).

[0090] An exemplary thermoelectric device comprises an array of couples sandwiched between two substrates. Each couple comprises one n-type and one p-type semiconductor. The couples are configured such that they are connected electrically in series, and thermally in parallel. The two substrates, which provide the platform for the connected couples, may be metals or metallized ceramics to facilitate heat transfer. A thermoelectric device may function singularly or in groups with series, parallel or series/parallel electrical connections depending on the desired level of heat transfer needed to activate the particular shape memory material of the reconfigurable pad 14.

[0091] The same semiconductor composition can be doped to form both members of the couple or two different semiconductor compositions can be used. A good semiconducting thermoelectric material is measured by its "figure of merit" or ZT , wherein T is the temperature and Z is defined as:

$$Z = S^2 / \rho K$$

wherein S is the Seebeck coefficient (ratio of the open-circuit voltage to the temperature difference between the hot and cold junctions of a circuit), ρ is the electrical resistivity, and K is the thermal conductivity. Desirably, the semiconductor has a ZT greater than or equal to about 0.5 at the given training temperature for the particular shape memory material used in the reconfigurable pad 14. Semiconducting materials suitable for use with the fixture devices disclosed herein include alloys of lead, bismuth, and/or antimony with tellurium and/or selenium (e.g., Bi_2Te_3 , PbTe , SbTe , BiSb , $\text{Bi}_{1.5}\text{Sb}_{0.5}\text{Te}_3$, PbSeTe , and the like); CsBi_4Te_6 ; SiGe ; MnTe ; filled skutterudites (e.g., $\text{CeFe}_4\text{Sb}_{12}$ and the like); $\text{XeIr}_4\text{Sb}_{12}$, $\text{Sr}_8\text{Ga}_{16}\text{Ge}_{30}$; Chevrel compounds (e.g., $\text{Cu}_{3.1}\text{Mo}_6\text{Se}_8$, $\text{Cu}_{1.38}\text{Fe}_{0.66}\text{Mo}_6\text{Se}_8$, and $\text{Ti}_{0.9}\text{Mo}_6\text{Se}_8$, and the like); and the like. One skilled in the art in view of this disclosure can determine which compositions would be appropriate for use in the fixture device 10 based on the particular shape memory materials of the reconfigurable pad 14. For example, Bi_2Te_3

has a ZT of 1.0 at 300 degrees Kelvin (K) and PbTe has a ZT of 0.9 at 500 K, both of which may be used with an SMP- or SMA-based reconfigurable pad 14.

[0092] A fixture device 10 incorporating a thermoelectric unit, as the activation device, in operative communication with the reconfigurable pad 14 is shown in Figure 8. The thermoelectric unit 24 is interposed between the base member 12 and the reconfigurable pad 14. A controller (e.g., a power supply) 28 is in electrical communication with the thermoelectric unit 24. Optionally, the controller 28 may include a temperature-measuring device (e.g., a thermocouple) in operative communication with the thermoelectric unit 24 and/or the reconfigurable pad 14 as a means of providing feedback to the controller 28.

[0093] An optional adhesion layer 26 may be used to further improve the bonding strength between the reconfigurable pad 14 and the thermoelectric unit 24. Suitable materials for use in the adhesion layer 26 include electrically conductive polymer adhesives, metallic films (e.g., titanium, chromium, alloys comprising titanium or chromium, and the like), organosilane compounds, and the like.

[0094] In operation of a fixture device 10 that makes use of a thermoelectric unit 24, a current is passed through the thermoelectric unit 24 in a first direction effective to heat the shape memory material of the reconfigurable pad 14 to the training temperature. The reconfigurable pad 14 is then pressed against the workpiece 16 with a force (F_1) and made to deform such that it sufficiently conforms to the contoured surface of the workpiece 16, as shown in Figures 2 and 6.

[0095] The reconfigurable pad 14 is then cooled below the training temperature by reversing the direction of the current passed through the thermoelectric unit 24. At this point, as illustrated in Figures 3 and 7, the reconfigurable pad 14 retains the configuration 'taught' during the training step even after it has cooled down to the regular working temperature and is suitable for fixturing workpieces 16 having the trained configuration. The next training step, or a reset step, can be carried out by passing a current through the thermoelectric unit 24 in the first direction again effective to heat the shape memory material of the reconfigurable pad 14 to the training temperature.

[0096] In an advantageous feature of using a thermoelectric unit 24, a temperature gradient in the shape memory material may be established (e.g., by reversing the direction of the current), while it is in the heated state (i.e., at or above the training temperature) but before the reconfigurable pad 14 is brought in contact with the training surface. This temperature gradient desirably results in a higher temperature on the surface of the reconfigurable pad 14 to be trained, and a lower temperature on an inner (i.e., interior to the surface to be trained) portion. In this manner, the colder portion of the shape memory material, and thus the reconfigurable pad 14, retains its shape and rigidity while the hotter portion is trained under compression. The temperature gradient permits appropriate temperature control, which can be beneficial if the reconfigurable pad 14 and training surface have different thermal masses and temperatures. For example, establishing the temperature gradient can help prevent melting or delamination/separation of a shape memory polymer reconfigurable pad 14 from the base member 12.

[0097] Another fixture device 10 incorporating a thermoelectric unit 24 is shown in Figure 9. The fixture device 10 includes a chamber 30 interposed between the reconfigurable pad 14 and the base member 12. The chamber 30 includes an inlet 32 (in this embodiment two inlets 32 and 34) and an outlet 36 through which air may flow. The thermoelectric unit 24, which is in electrical communication with the controller 28, is disposed inside the chamber such that two portions are defined by the thermoelectric unit 24. On one side of the thermoelectric unit 24 is a heat sink 38, and on an opposite side of the thermoelectric unit is a cold sink 40. The heat sink 38 and the cold sink 40 are downstream of the inlets 32 and 34. The reconfigurable pad 14 is disposed on the chamber outlet 36.

[0098] In operation of the fixture device 10 shown in Figure 9, a current is passed through the thermoelectric unit 24 effective to heat the heat sink 38 (and in turn cool the cold sink 40). Air, which is forced through the chamber 30 via chamber inlet 32, is heated by the heat sink 38 and exits the chamber outlet 36 where it contacts the reconfigurable pad 14. Once the shape memory material of the reconfigurable pad 14 is heated to the training temperature, the reconfigurable pad 14 can be pressed against the workpiece 16 with a force (F_1) and made to deform such

that it sufficiently conforms to the contoured surface of the workpiece 16, as shown in Figures 2 and 6.

[0099] The reconfigurable pad 14 is then cooled below the training temperature while still under F_1 . The reconfigurable pad 14 can be naturally cooled by shutting off the air supply to the chamber inlet 32 and discontinuing the current passing through the thermoelectric unit 24. Alternatively, the reconfigurable pad 14 can be cooled by shutting off the air supply to chamber inlet 32, and forcing air through the chamber 30 via chamber inlet 34 where it is cooled by the cold sink 40 and exits the chamber outlet 36 to contact the reconfigurable pad 14. At this point, as illustrated in Figures 3 and 7, the reconfigurable pad 14 retains the configuration 'taught' during the training step even after it has cooled down to the regular working temperature and is suitable for fixturing workpieces 16 having the trained configuration. The current passing through the thermoelectric unit 24 and any air flowing through the chamber 30 can be discontinued after the training step. Subsequent training steps can be performed in a similar fashion.

[00100] In one embodiment, the fixture device 10 may further comprise a valve (e.g., a check valve or a flapper valve) 42, which is downstream of the thermoelectric unit 24, heat sink 38, and cold sink 40. The valve can prevent air, while being forced through the chamber 30, from flowing into one inlet, across the chamber, and out through the other inlet.

[00101] In another embodiment, the fixture device 10 may further comprise a perforated plate 44 disposed between the chamber outlet 36 and the reconfigurable pad 14. The perforated plate 44 provides an additional support structure for the reconfigurable pad 14 to rest upon, while permitting air to flow from the chamber 30 to heat or cool the reconfigurable pad 14.

[00102] Referring now to Figures 8 and 9, the fixture device 10 is shown in operable communication with controller 28. A plurality of sensors 46 is in electrical communication with the controller 28. The sensors 46 measure various parameters associated with operation of the fixture device including, but not limited to, positions of the components defining the fixture device 10 (e.g., the reconfigurable

pad 14, the workpiece 16, opposing pad if present, and the like), temperatures of the reconfigurable pad 14 and /or the workpiece 16 and/or the environment in which the fixture device is operated, the magnitude of forces being applied during support or clamping applications, the status of the individual components that can be actively monitored, and the like. Feedback from the sensors 46 to the controller 28 can be used to ensure that the fixture device 10 operates in the intended manner. Using the appropriate algorithms, the controller 28 can, based on the values obtained from the sensors, actuate one or more actuators 48 to perform a desired function so as to regulate the desired parameter as desired for the particular application. The sensors 46 are not intend to be limited to any particular position or form. For example the sensors 46 can be integrated with or externally disposed about the components defining the fixture device 10. In exemplary embodiments, the fixture device may also be completely or partially manually controlled. The manual control may either be only for tuning the process during setup, trying out different materials and/or system designs, or may be the mode of operation for limited volume production runs.

[00103] Various types of sensors 46 are known in the art that can be suitably used to monitor the particular parameter. For example, sensors for detecting a position and an orientation of the reconfigurable pad 14 and/or the workpiece 16 can include a joint coordinate based sensor, e.g., encoders for rotary joints and linear displacement transducers for prismatic joints. In other exemplary embodiments, the sensors 46 can include vision-based sensors 46 that infer the position and orientation of the rigid end-effector using a set of reference markers that are associated with a reference coordinate system. Other suitable positional sensors can include limit switches that detect end-of-travel along the various axes of movement that the fixture device or workpiece 16 can travel in. Again, the particular sensor employed for monitoring the particular parameter is not intended to be limited to any particular type.

[00104] Suitable sensors for measuring forces include the use of load cells that can be mechanically configured in series with the fixture device 10. Alternatively, one or more strain gauges mounted on elastic elements can be mechanically coupled to the fixture device 10 to measure the force levels. Measuring force levels may be desirable in some applications such as clamping applications as

well as force levels exerted by the reconfigurable pad 14 on a workpiece in support applications. The forces are preferably measured as close to the working surface of the reconfigurable pad 14 as can be reliably and accurately done. In other embodiments, the forces can be inferred from the torque on the base member 12 or other portions of the fixture device 10. Sensors based on indirect measurement of the forces may also be suitably used. For example, an input signal (e.g. current in electric clamps, air pressure in pneumatic clamps, etc.) to the actuator 48 can be utilized, which is responsible for producing a corresponding force.

[00105] Suitable temperature sensors include both contact and non-contact type sensors. For example, suitable contact based sensors include, but are not intended to be limited to, thermocouples, resistance temperature detectors (RTD), and bulb and capillary devices. Non-contact based temperature sensors include, but are not intended to be limited to, pyrometers, infrared sensors, and fiber-optic temperature sensors (e.g., fluoro-optic). The temperature sensors can be positioned to detect the temperature of the reconfigurable pad 14, the workpiece 16, the environmental temperature in and about the fixture device as well as any other component where it may be desirable to measure temperature, e.g., the base member. Similarly, the temperature sensor can be employed for bulk measurement or for salient points within the fixture device.

[00106] By way of example, salient points of the reconfigurable pad 14 where temperature measurement may be desirable include measuring the last portions of the reconfigurable pad 14 that exceed a specified temperature when heating the reconfigurable pad 14. Measuring the last portions of the reconfigurable can be important in some applications since the reconfigurable pad may not be uniformly dimensioned such that uniform heating does not occur. Measuring the salient points to insure the reconfigurable pad has reached and/or exceeded the specified temperature can prolong operating lifetimes as well as ensure correct operation. Likewise, it may be desirable to measure the salient points associated with the last portions of the reconfigurable pad 14 that are cooled to below a specified temperature when cooling the reconfigurable pad 14. The location of the salient points may depend on the geometry of the reconfigurable pad 14, the method of heating and/or

cooling the reconfigurable pad 14, the system configuration, and/or the properties of the material of which the reconfigurable pad 14 is comprised.

[00107] The bulk temperature measurement of the reconfigurable pad 14 can be measured by monitoring changes in a bulk property, (e.g., stiffness changes, coloration changes, and/or the like), which is then correlated to the temperature. For example, thermochromic materials can be embedded in the reconfigurable pad 14 (e.g. either randomly distributed or specifically located at the salient points). As is appreciated by those in the art, thermochromic materials undergo a change in color, hue, and/or opacity in response to a change in temperature. The thermochromic materials can be chosen such that a specific temperature (e.g. T_{form} or T_{set}) is flagged by these indicators, or a range of different temperatures can be inferred from the different colors/hues/opacities specific to one or more of the thermochromic materials.

[00108] Temperature measurement of the environment around the fixture device 10, and especially in and about the vicinity of the reconfigurable pad 14, can provide useful information related to heat loss by natural and/or forced convection, and/or radiation from exposed surfaces of the reconfigurable pad 14. If the surface temperatures of the reconfigurable pad 14 can be reliably measured then the measurement of the environmental temperature can be used to ensure that the fixture device 10 is functioning properly. However, if the surface temperatures of the reconfigurable pad 14 cannot be measured reliably then the surface temperature has to be inferred from the source temperature, the thermo-physical properties of the material, the surface heat transfer characteristics, and the environmental temperature. Instances where the surface temperature of the reconfigurable pad 14 may not be able to be reliably measured include, for example, when the thermocouples begin to fail as result of cycle fatigue or the like, when there is an accumulation of debris on the surface of the reconfigurable pad 14 which may make optical measurements difficult, and the like.

[00109] Direct or indirect temperature measurement of the workpiece 16 may also be useful in applications where the workpiece 16 has a large thermal mass. In these applications, when the workpiece 16 is brought into contact with the

reconfigurable pad 14 the working surface of the reconfigurable pad 14 is subjected to the temperature of the workpiece 16. Using a reconfigurable pad formed of a shape memory polymer as an example, if the workpiece 16 is colder than the working surface of the reconfigurable pad 14, a rapid local cooling of the working surface can occur. If such a rapid cooling occurs while the reconfigurable pad 14 is being trained, gradients in elastic modulus can occur and cause local failure at/near the work surface. Likewise, if a hot workpiece 16 is brought into contact with the working surface of the reconfigurable pad 14 which is cooler than the workpiece 16, localized heating can occur and if the workpiece 16 temperature is above the T_{g1} , the heating can cause the reconfigurable pad 14 to lose its set shape. Additionally, if the workpiece 16 causes the temperature of the reconfigurable pad 14 to rise above T_{max} it may cause irreversible damage to the reconfigurable pad 14. For at least these reasons, it is desirable to measure the temperature of the workpiece 16, which can be measured directly off the workpiece 16 (e.g., a thermocouple can be in contact with the workpiece 16 or via a non-contact temperature sensor such as an IR sensor), or alternatively, the temperature of the workpiece 16 can be inferred from the finish temperature of the previous process, the environmental temperature, or the like.

[00110] The particular type of temperature sensor employed will generally depend on the range of temperatures to be measured, the response time for the measuring technique, the sensors susceptibility to noise and perturbing inputs, the cost of the sensor, and the like. An additional consideration especially for measuring the temperatures at the salient points on or in the reconfigurable pad 14 is that the measurement technique should be compatible with the large deformations that the reconfigurable pad 14 can experience during operation (e.g., in some applications local strains can approach 100%).

[00111] In other embodiments, the reconfigurable pad 14 is initially heated at a high heating rate, subject to the constraints given below, and the heating rate is gradually decreased as the desired operating temperature of the reconfigurable pad 14 is achieved. A similar approach may be used when cooling the reconfigurable pad 14 as well. For example, the controller 28 can employ an ON/OFF control strategy, wherein the temperature of the heat source and/or the flow rate of the transfer medium is fixed and variation in the heat flow rate is achieved by switching

the heat flow ON or OFF. Another approach comprises switching between multiple levels of heat flow rate between OFF and (fully) ON. For example, a pulse width modulation scheme may be used wherein the duration of the ON and OFF pulses are controlled to achieve the desired heat flow rate.

[00112] The maximum permissible temperature for any material in the system which comes into contact with the medium or the power rating of the heating source places a bound on the maximum temperature of the medium. The flow capacity of the system (e.g., of the fan used to generate the flow) places a constraint on how much improvement in the efficiency of the heat transfer can be practically achieved. The thermal diffusivity of the material defining the reconfigurable pad 14 determines how quickly heat can be propagated into the material. If more heat is supplied than can be diffused into the reconfigurable pad 14, the reconfigurable pad 14 surface will overheat and lead to its failure. When the reconfigurable pad 14 is being cooled, if the cooling rate is very high (e.g., faster than the viscoelastic stress relaxation time constant) the stresses in the material are unable to relax before the SMP reverts to its stiff form, which may lead to failure of the reconfigurable pad 14.

[00113] In other embodiments, the fixture device may include so-called end of life (EOL) sensors. The particular parameters measured by the EOL sensors can vary and can be utilized to measure the state of the reconfigurable pad 14. For example, the EOL sensor can measure a parameter indicative of the ability of the reconfigurable pad 14 to maintain a trained configuration as well as the ability of the reconfigurable pad 14 to deform to a desired configuration. In addition, the EOL sensor can be configured to provide information about the reconfigurable pad 14 related to wear, thermo-mechanically induced fatigue, thermally induced oxidation, cold cracking, plastic yielding, and the like. Additionally, a statistical analysis of information provided from the parameters sensed by the EOL sensor can be used to predict a failure of the reconfigurable pad 14. For example, different types of failures may be associated with different characteristic sensor data sequences and accumulated knowledge of the use of the reconfigurable pad 14 can be used to compute expected time to failure. Simple counter(s) can be used to track the number of training and use cycles. When either of these numbers exceeds corresponding thresholds (obtained from in-plant use or lab testing experience), the reconfigurable pad 14 may be deemed

to have exhausted its useful life. This criterion can be used independently or in conjunction with other indicators (e.g., such as those described above) to flag a maintenance request. Additionally, a preventive maintenance schedule may be developed using the information tracked by the counters along with the condition of the reconfigurable pad 14 to recommend a pre-emptive grip change, as may be desired for some applications.

[00114] The controller 28 itself includes a processor that receives status signals from the plurality of sensors 46 and transmits command signals to the actuator 48. In those embodiments employing the thermoelectric unit 24, the command signals can be transmitted to the thermoelectric unit 24 as well. The controller 28 may also receive an operation signal from a user that is indicative of a desired action of the fixture device 10. In exemplary embodiments, the controller 28 includes control logic and/or algorithms to provide a variety of control functions. Various control functions may include, but are not intended to be limited to, a heat function, a cool function, a position function, a locate function, open and close functions for clamping applications, a status function, a reset function, and the like. Each function receives specific status signals from the various sensors 46 and responsively transmits command signals to the particular actuator 48 responsible for the programmed function. These functions may be used independently, in combination, or as sub-functions of a larger control algorithm. For example, a train function for training the reconfigurable pad 14 may intelligently execute the open, locate, position, heat, close, and cool functions to train the reconfigurable pad 14 to the shape of a workpiece 16 or a master surface. Furthermore, the controller 28 may include a memory that allows the controller 28 to store received status signals as variables that may be accessed by the one or more functions.

[00115] By way of example, the heat function can be used to selectively heat the reconfigurable pad 14. The heat function may receive several input parameters (i.e., status signals) from the various temperature sensors that provided temperature information. For example, depending on the application, the temperature information may include the current temperature of the workpiece 16, the temperature of the reconfigurable pad 14, the temperature of the salient points of the reconfigurable pad 14, and the like. Based on the input status signals as well as the

particular algorithm programmed, the heat function can then maintain and/or modulate the temperature. Temperature modulation can include additional variables such as a total heating time, a current heating rate, a maximum heating time, a maximum heating rate, a maximum allowable temperature, the characteristics of the reconfigurable pad 14, and the like. Responsive to the input parameters and variables, the heat function responsively transmits command signals to the particular actuator and/or heater/cooler to provide the programmed function. In other embodiments, process sequence foreknowledge may be utilized (e.g., start heating at the end of a previous cycle when it is known that a reconfiguration is needed on the next cycle).

[00116] Various task level control strategies will now be described. The control strategies are exemplary and are not intended to be limited to that described. The fixture device 10 may be controlled through the use of these tasks, which a user or a larger control system may execute by transmitting an operation signal to the controller 28. The tasks include, but are not limited to, a position task, a train task, a set task, a clamp task, and the like. Upon receiving the operation signal, the controller 28 responsively executes one or more functions. The controller 28 may communicate with a larger control system electronically via various means. In other exemplary embodiments, the controller 28 may include a display and an input device for receiving operation signals from a user and displaying information such as error flags to the user.

[00117] In one embodiment related to heating the reconfigurable pad, the heat function is programmed to check that the current heating condition is less than the maximum safe heating condition for the reconfigurable pad 14, the maximum temperature ($T_{\max}$) is less than the maximum allowable temperature (T_{all}); the total heating time (t_H) in the heating cycle is less than the maximum heating time (t_{HM}) and that at least one of the following conditions is met: the temperature of the work surface (T_{ws}) of the reconfigurable pad 14 is less than the forming temperature (T_{form}); the minimum temperature ($T_{\min}$) is less than a factor of T_{form} ; or the temperature at stress raiser (T_{sr}) is less than a factor of T_{form} . The temperature at stress raiser refers to the temperature at regions within the grip that experience high strains and/or stresses during the training or use of the grips. Likewise, before decreasing the heating condition of the reconfigurable pad, the heat function may check that at least

one of the following conditions is met: the T_{ws} of the reconfigurable pad 14 is greater than a factor of T_{form} ; the T_{min} is greater than a factor of T_{form} ; the T_{sr} is greater than a factor of T_{form} ; or that the T_{max} is greater than T_{all} .

[00118] In one embodiment related to cooling the reconfigurable pad, the cool function may be programmed to first check that the current cooling condition is less than the maximum cooling condition and the time in the cooling cycle (t_c) is less than the maximum cooling time (t_{CM}); and that at least one of the following conditions is met: the T_{ws} of the reconfigurable pad 14 is greater than the setting temperature (T_{set}); or the T_{max} is greater than a factor of T_{set} .

[00119] In one embodiment related to the position function for positioning the reconfigurable pad 14 and/or the workpiece 16, the position function may receive several input parameters related to, for example, the current position of the reconfigurable pad 14, the current position of the workpiece 16, and the like. The position parameter may be defined by a Boolean variable, which can be set to 1 if the current position of the workpiece 16 and/or the reconfigurable pad 14 is in the desired position. In exemplary embodiments, the desired positions of the workpiece 16 and the reconfigurable pad 14 are variables stored by the controller 28, which the position function may access. The controller 28 responsively transmits command signals to the actuators 48 to adjust the positions, if needed, of the workpiece 16 and/or the reconfigurable pad 14.

[00120] In one embodiment, before moving the reconfigurable pad 14 the position function may be programmed to first check that the reconfigurable pad 14 is not in use. If the reconfigurable pad is not in use, the position function may continue to move the reconfigurable pad 14 and/or the workpiece 16 until the position status parameter indicates the reconfigurable pad 14 and the workpiece are in the desired position.

[00121] The locate function can be used to check if the reference, e.g., workpiece 16 or master, is disposed against the working surface of the reconfigurable pad 14. The locate function may receive several input parameters including, but not limited to, a location flag, the position status, a training flag, and the like. For

example, the location flag and/or training flag can be a Boolean variable set to 1 if the workpiece 16 is disposed against the working surface of the reconfigurable pad 14 and remains 0 otherwise. The locate function can provide the location flag responsive to the position of the workpiece 16 and/or the reconfigurable pad 14.

[00122] In one exemplary embodiment, the locate function first checks if the position status indicates that the reconfigurable pad 14 and/or the workpiece 16 (or master surface) is properly positioned and that the reconfigurable pad 14 is not in use. If the above conditions are met, a flag can be set that indicates the reconfigurable pad 14 is in the training state or the reconfigurable pad is trained, for example, by executing the close function. Additionally, if the T_{ws} of the reconfigurable pad 14 is less than T_{form} or T_{min} is less than a factor of T_{form} , the locate function can be programmed to execute the heat function to increase the temperature of the reconfigurable pad for training. The locate function can also be programmed to increase the forces being exerted by or on the reconfigurable pad 14 while the workpiece 16 or master surface is properly positioned and the current force is less than the maximum force. In embodiments where a training cycle counter is used, the locate function may also increment the training cycle counter.

[00123] The open and close functions can be used in the embodiments where the reconfigurable pad 14 is incorporated in a clamp. Generally, the controller 28 uses the open and close functions to engage, release, and set the force exerted by the reconfigurable pad 14 on the workpiece 16 or master surface for training of the reconfigurable pad 12. For example, the open function can be programmed to check that the reconfigurable pad 14 is in the closed state and if so, open the reconfigurable pad 14 unless the training flag is set and the workpiece temperature is greater than the shape setting temperature. If both of these conditions are not met, the open function sets an error flag and leaves the reconfigurable pad 14 in the closed state. The close function can be programmed to receives a desired force parameter and set the reconfigurable pad 14 in the closed state with the force exerted by the reconfigurable pad 14 equal to the desired force parameter.

[00124] The maximum value of force exerted by the reconfigurable pad 14 is generally dependent on the kinematics of the clamp mechanism and the

force/torque capacity of the actuator. Adjusting the force/torque capacity of the actuator (e.g., by increasing the air pressure in a pneumatic clamp) or by adjusting the kinematic parameters of the actuator mechanism can enable a change in the maximum force. If the maximum force is controllable, different force levels may be selected for training and for use of the trained reconfigurable pad 14. For example, using a reconfigurable pad 14 formed of SMP as an example, during training reconfigurable pad 14 has a low elastic modulus and can be deformed much more easily than during actual use when the material has a significantly higher elastic modulus. Because of this, a lower maximum force can be used during shape training than during regular use. In embodiments where the force can be varied with respect to time, a control strategy that minimizes the impact force between the reconfigurable pad 14 and the workpiece 16 or master surface can be utilized to ensure a smooth and gradual increase in the force applied either to or by the reconfigurable pad 14.

[00125] The status function can be programmed to provide information as to whether the reconfigurable pad 14 has reached the end of its useful life by checking the value of a worn state variable. By way of example, the worn state variable can be a Boolean variable set to 1 when an end of life variable indicates that the reconfigurable pad 14 has reached the end of its useful life. The status function can also be programmed to check if the environmental temperature is greater than the training temperature of the reconfigurable pad 14. If the environmental temperature exceeds a predetermined value, an error flag may be set indicating that the function could not be properly executed. In this case, the cool function can be called to reduce the temperature of the reconfigurable pad 14 and the status function can be re-executed.

[00126] In an exemplary embodiment, the status function can be programmed to indicate that the pad needs to be replaced before the next cycle (train or use) if at least one of the following conditions is met: a manual override is activated by the operator (locally or remotely) to flag a pad replacement; the training cycle counter is greater than or equal to the maximum number of training cycles; the use counter is greater than or equal to the maximum number of use cycles; or the worn variable indicates that the reconfigurable pad is at the end of its useful life.

Additionally, the status function can be programmed to set an error flag if the ambient temperature (T_{amb}) is greater than T_{set} .

[00127] The reset function can be used to reset several parameters and variables stored by the controller 28 to reflect that a new reconfigurable pad 14 has been installed in the fixture device 10. By way of example, the reset function may reset the worn state variable to 0 to indicate that the new reconfigurable pad is not worn. Additionally, the reset flag may reset any counters that are used to track the use of the reconfigurable pad 14 as may be desired for various applications.

[00128] Referring now to Figure 10, a flow chart of an exemplary control process for using the reconfigurable pad 14 is generally depicted at 50. The first step in the control process 50 is to check the status of if the reconfigurable pad 14, as shown at process step 52. If the reconfigurable pad 14 is at or near the end of its useful life, the control process can be designed to set a maintenance request flag (as shown at process step 54) indicating that the reconfigurable pad 14 needs to be replaced or repaired. Once the reconfigurable pad 14 has been replaced, the control process 50 may reset any counters or variables and restart the control process 50, as shown at process step 56. If the status function indicates that the environmental temperature exceeds a predetermined value, the control process 50 may execute the cool function. After the control process successfully passes the status check in step 52, the control process 50 proceeds to process step 58.

[00129] At process step 58, the control process 50 determines if the reconfigurable pad 14 needs to be trained. If the reconfigurable pad 14 does not need to be trained the control process 50 proceeds to process step 62. If the reconfigurable pad 14 needs to be trained the control process 50 proceeds to process step 60, where the reconfigurable pad 14 is then trained in the manner previously described. During process step 60, the reconfigurable pad 14 can be trained to take a specific shape using the approaches described earlier. Once the reconfigurable pad 14 is trained, the control process 50 proceeds to process step 62, whenever the reconfigurable pad 14 is used to perform a desired function. During process step 62, the control process 50 may execute various functions including, but not limited to, the locate function, the position function, the open function, the close function, or the like.

[00130] As previously described, in addition to support applications the fixture device 10 may be employed for clamping applications and may include an opposing pad. Depending on the application, the opposing pad may be a reconfigurable pad constructed of a secondary shape memory material (of the same or different shape material) and be disposed on an opposing base member. The opposing pad may also include a plurality of sensors 46 in electrical communication with the controller 28. Similarly, the opposing base member may include a secondary actuator in electrical communication with the controller 28. In other embodiments, the opposing pad 14 may include a thermoelectric unit that may be used to modulate the temperature and environment of the opposing pad 14.

[00131] In one embodiment, two fixture devices 10 are used for every clamp location, one of the reconfigurable pads 14 can be used for fixturing the current workpiece 16 while the other reconfigurable pad 14 is simultaneously being trained for the next workpiece. When the processing of the current workpiece 16 is completed the currently active fixture devices 10 is moved out of the work location. The other fixture device 10 is moved in to process the next workpiece 16 and becomes the currently active fixture device 10, and the above process can be repeated. A reduction of the effective reconfiguration times (i.e. the reconfiguration time that contributes to the overall time spent by the workpiece 16 at the work station) can be achieved by this approach.

[00132] As would be apparent to those skilled in the art, the training and setting of the shape of the reconfigurable pad 14 can be done online or offline. In the online approach, the reconfigurable pad 14 is trained directly on the workpiece 16 that it will be used to fixture. In the offline approach, the reconfigurable pad 14 is trained either on a master surface, which is an inverted reproduction of the shape that is to be imparted to the reconfigurable pad 14. Online reconfiguration does not need additional hardware such as the master surface used in the offline approach and hence may be used to provide a self-contained, and less expensive reconfigurable clamp system. Offline training and use of the reconfigurable pad 14 are conceptually distinct and this separation frees the training process from some of the restrictions that are associated with training in the online reconfiguration approach. Generally, offline

training results in a greater flexibility and choice of methods that can be used for heating and cooling the grips.

[00133] As described above, the present disclosure can be embodied in the form of computer-implemented processes and apparatuses for practicing those processes. For example, the present disclosure can be embodied in the form of computer program code containing instructions embodied in tangible media, such as floppy diskettes, CD ROMs, hard drives, or any other computer-readable storage medium, wherein, when the computer program code is loaded into and executed by a computer, the computer becomes an apparatus for practicing the disclosure. The present disclosure can also be embodied in the form of computer program code, for example, whether stored in a storage medium, loaded into and/or executed by a computer, or transmitted over some transmission medium, loaded into and/or executed by a computer, or transmitted over some transmission medium, such as over electrical wiring or cabling, through fiber optics, or via electromagnetic radiation, wherein, when the computer program code is loaded into and executed by a computer, the computer becomes an apparatus for practicing the invention. When implemented on a general-purpose microprocessor, the computer program code segments configure the microprocessor to create specific logic circuits.

[00134] While the disclosure has been described with reference to exemplary embodiments, it will be understood by those skilled in the art that various changes may be made and equivalents may be substituted for elements thereof without departing from the scope of the disclosure. In addition, many modifications may be made to adapt a particular situation or material to the teachings of the disclosure without departing from the essential scope thereof. Therefore, it is intended that the disclosure not be limited to the particular embodiment disclosed as the best mode contemplated for carrying out this disclosure, but that the disclosure will include all embodiments falling within the scope of the appended claims.

CLAIMS

1. A fixture device (10), comprising:

a base member (12);

a reconfigurable pad (14) disposed on the base member (12), wherein the reconfigurable pad (14) comprises a shape memory material configured to selectively conform to a surface contour of a workpiece (16); and

an activation device (24) in operative communication with the shape memory material.

2. The fixture device (10) of Claim 1, further comprising:

a controller (28) in operable communication with at least one of the reconfigurable pad (14), the activation device (24), and the base member (12);

a plurality of sensors (46) for sensing a parameter associated with at least one of the reconfigurable pad (14), the base member (12), the fixture device (10), and the workpiece (16), wherein the plurality of sensors (46) is in operable communication with the controller (28); and

an actuator (48) in operable communication with the controller (28) and the at least one of the reconfigurable pad (14), the base member (12), the fixture device (10), and the workpiece (16).

3. The fixture device (10) of any of the preceding Claims, wherein the shape memory material is a shape memory alloy, a shape memory polymer, a baroplastic, a shape memory ceramic, a composite comprising a shape memory alloy and a shape memory polymer, a composite of one of the foregoing and a non-shape memory material, or a combination comprising at least one of the foregoing.

4. The fixture device (10) of any of the preceding Claims, further comprising an opposing pad, wherein the opposing pad and the reconfigurable pad (14) are configured to fixture the workpiece (16) therebetween.

5. The fixture device (10) of any of the preceding Claims, wherein the opposing pad is a reconfigurable opposing pad comprising a shape memory material configured to selectively conform to an opposing surface contour of the workpiece (16).

6. The fixture device (10) of any of the preceding Claims, wherein the shape memory material of the reconfigurable opposing pad is a shape memory alloy, a shape memory polymer, a baroplastic, a shape memory ceramic, a composite comprising a shape memory alloy and a shape memory polymer, a composite of one of the foregoing and a non-shape memory material, or a combination comprising at least one of the foregoing.

7. The fixture device (10) of any of the preceding Claims, wherein the shape memory material of the reconfigurable opposing pad is in operative communication with the activation device (24) or a different activation device (24).

8. The fixture device (10) of any of the preceding Claims, further comprising an opposing base member onto which the opposing pad is disposed.

9. The fixture device (10) of any of the preceding Claims, further comprising a locator pin (15) disposed on the base member (12).

10. The fixture device (10) of any of the preceding Claims, wherein the plurality of sensors (46) are configured to sense a parameter associated with at least one of the opposing pad, opposing base member, and locator pin (15).

11. The fixture device (10) of any of the preceding Claims, wherein the sensed parameter associated with at least one of the reconfigurable pad (14), the base member (12), the fixture device (10), the workpiece (16), the opposing pad, the opposing base member, and the locator pin (15) is at least one of the following:

a temperature associated with at least one of the reconfigurable pad (14), the base member (12), the fixture device (10), and the workpiece (16);

a temperature associated with an environment of the fixture device (10);

a position of the reconfigurable pad (14), the base member (12), and the workpiece (16);

a location of the reconfigurable pad (14), the base member (12), and the workpiece (16);

a force applied to the reconfigurable pad (14), the base member (12), the fixture device (10), and the workpiece (16); and

a status of the reconfigurable pad (14)

12. The fixture device (10) of any of the preceding Claims, wherein at least one of the activation device (24) and the different activation device (24) is a thermoelectric unit (24).

13. A computer program product for fixturing a workpiece (16), the computer program product comprising:

a storage medium readable by a processing circuit and storing instructions for execution by the processing circuit for facilitating a method comprising detecting a parameter associated with a reconfigurable fixturing device with at least one sensor (46) to produce at least one parameter defining signal; processing the at least one parameter defining signal from the at least one sensor (46) and sending an output signal to a control interface, wherein the output signal is effective to perform a function comprising at least one of a heat function, a cool function, a position function, a location function, open and close functions, a resetting function and a status-check function, wherein the reconfigurable fixturing device comprises a reconfigurable pad (14) formed of a shape memory material.

14. The computer program product of Claim 13, wherein the parameter defining signal is indicative of a position of the workpiece (16) and the reconfigurable pad (14), a temperature of the workpiece (16) and the reconfigurable pad (14), an environmental temperature associated with the fixturing device, a force level of the reconfigurable pad (14) against the workpiece (16), a status of the reconfigurable pad (14), and a location of the workpiece (16) and the reconfigurable pad (14).

15. The computer program product of any of the preceding Claims, wherein the shape memory material is a shape memory alloy, a shape memory polymer, a baroplastic, a shape memory ceramic, a composite comprising a shape memory alloy and a shape memory polymer, a composite of one of the foregoing and a non-shape memory material, or a combination comprising at least one of the foregoing.

16. A process, comprising:

contacting a surface of at least one workpiece (16) with a reconfigurable pad (14) of a fixture device (10), wherein the reconfigurable pad (14) comprises a shape memory material configured to conform to the surface of the at least one workpiece (16); and

fixturing the contacted workpiece (16).

17. The process of Claim 16, further comprising conforming the reconfigurable pad (14) of the fixture device (10) to the surface of the at least one workpiece (16) prior to the contacting.

18. The process of any of the preceding Claims, wherein the conforming comprises:

activating the shape memory material;

applying a force to the reconfigurable pad (14) effective to deform the reconfigurable pad (14) from an original shape to a shape conforming to the surface of the workpiece (16) or a training surface; and

deactivating the shape memory material.

19. The process of any of the preceding Claims, wherein activating the shape memory material comprises applying at least one of heat, moisture, and light to the shape memory material, and wherein deactivating the shape memory material comprises discontinuing the at least one of the heat, the moisture, and the light.

20. The process of any of the preceding Claims, further comprising resetting the reconfigurable pad (14) to a different shape corresponding to a surface of at least one different workpiece (16).

21. The process of any of the preceding Claims, wherein the resetting comprises activating the shape memory material without an applied load.

22. The process of any of the preceding Claims, wherein the fixturing comprises supporting the workpiece (16) in a fixed position.

23. The process of any of the preceding Claims, wherein the contacting comprises disposing the workpiece (16) between the reconfigurable pad (14) of the fixture device (10) and an other pad of the fixture device (10), and the fixturing comprises clamping the workpiece (16) in a fixed position.

24. The process of any of the preceding Claims, wherein the other pad of the fixture device (10) comprises a shape memory material configured to conform to an other surface of the at least one workpiece (16).

25. The process of any of the preceding Claims, further comprising conforming the other pad of the fixture device (10) to the other surface of the workpiece (16) prior to the contacting.

26. The process of any of the preceding Claims, further comprising using a locating pin to provide information regarding location of the workpiece (16).

27. A process, comprising:

contacting a first surface of a first workpiece (16) with a reconfigurable pad (14) of a fixture device (10), wherein the reconfigurable pad (14) comprises a shape memory material configured to conform to the first surface of the first workpiece (16);

fixturing the contacted first workpiece (16);

conforming the reconfigurable pad (14) of the fixture device (10) to a second surface of a second workpiece (16);

contacting the second surface of the second workpiece (16) with the reconfigurable pad (14) of the fixture device (10); and

fixturing the second workpiece (16).

28. The process of Claim 27, further comprising resetting the reconfigurable pad (14) to an original shape prior to conforming.

29. A process for conforming a reconfigurable pad (14) of a fixture device (10) to a surface of at least one workpiece (16), the process comprising:

heating the reconfigurable pad (14) effective to increase a temperature of a shape memory material to or above a shape setting temperature;

applying a force to the reconfigurable pad (14) effective to deform the reconfigurable pad (14) from an original shape to a shape conforming to the surface of the at least one workpiece (16); and

cooling the shape memory material below the shape setting temperature.

30 The process of Claim 29, wherein the heating comprises resistive heating, contacting a heated fluid, inductive heating, microwave heating, exposing to laser light, thermoelectric heating, microwave heating, infrared heating, exposing to a flash lamp, convective heating, or a combination comprising at least one of the foregoing.

31. The process of any of the preceding Claims, wherein the applying comprises contacting the workpiece (16) to the heated reconfigurable pad (14).

32. The process of any of the preceding Claims, wherein the applying comprises contacting a master article with a shape substantially similar to the workpiece (16) to the heated reconfigurable pad (14).

33. The process of any of the preceding Claims, wherein the cooling comprises removing a heating source, free convective fluid cooling, forced convective fluid cooling, contacting a cooled fluid, thermoelectric cooling, or a combination comprising at least one of the foregoing.

34. A method for controlling a reconfigurable fixture device (10), comprising

receiving a status signal from a sensor (46) to a controller (28), wherein the sensor (46) is in operable communication with at least one of a base member (12), and a reconfigurable pad (14) disposed on the base member (12), wherein the reconfigurable pad (14) comprises a shape memory material configured to selectively conform to a surface contour of a workpiece (16);

receiving an operation signal from a user;

generating a command signal responsive to the status signal and/or the operation signal; and

transmitting the command signal from the controller (28) to at least one of an activation device (24) in operative communication with the shape memory material and an actuator (48) in operable communication with the base member (12).

35. The method of Claim 34, further comprising receiving a secondary status signal from a secondary sensor (46), wherein the secondary sensor (46) is in operable communication with an opposing pad, wherein the opposing pad and the reconfigurable pad (14) are configured to fixture the workpiece (16) therebetween; and wherein the command signal is generated responsive to the status signal, the operation signal, and/or the secondary status signal and is transmitted to at least one of the activation device (24), the actuator (48), and a secondary actuator (48) in operable communication with the opposing pad.

36. The method of any of the preceding Claims, wherein the opposing pad comprises a shape memory material and wherein the command signal is transmitted to a secondary activation device (24) in operative communication with the shape memory material of the opposing pad.

37. The method of any of the preceding Claims, wherein the status signal is indicative of at least one of the following:

a temperature associated with at least one of the reconfigurable pad (14), the base member (12), the fixture device (10), and the workpiece (16);

a temperature associated with an environment of the fixture device (10);

a position of the reconfigurable pad (14), the base member (12), and the workpiece (16);

a location of the reconfigurable pad (14), the base member (12), and the workpiece (16);

a force applied to the reconfigurable pad (14), the base member (12), the fixture device (10), and the workpiece (16); and

a status of the reconfigurable pad (14).

38. The method of any of the preceding Claims, wherein the secondary status signal is indicative of at least one of the following:

a temperature of the opposing pad;

a position of the opposing pad; and

a status of the opposing pad.

39. The method of any of the preceding Claims, wherein the command signal is indicative of at least one of a desired change in a temperature, a position of the reconfigurable pad (14), a position of the opposing pad, a force setting between the reconfigurable pad (14) and workpiece (16), an error flag, and whether the opposing pad and reconfigurable pad (14) are in an open position or a closed position.

40. A method (50) of using a reconfigurable fixture device (10), comprising:

transferring a workpiece (16) to a reconfigurable pad (14), wherein transferring the workpiece (16) comprises checking (52) a status of the reconfigurable pad (14); determining (58) if the reconfigurable pad (14) needs to be reconfigured;

locating and fixturing (62) the workpiece (16) against the reconfigurable pad (14), wherein locating and fixturing (62) the workpiece (16) comprises determining the location of the reconfigurable pad (14) and fixturing the workpiece (16) with the reconfigurable pad (14); and

performing an operation on the workpiece (16).

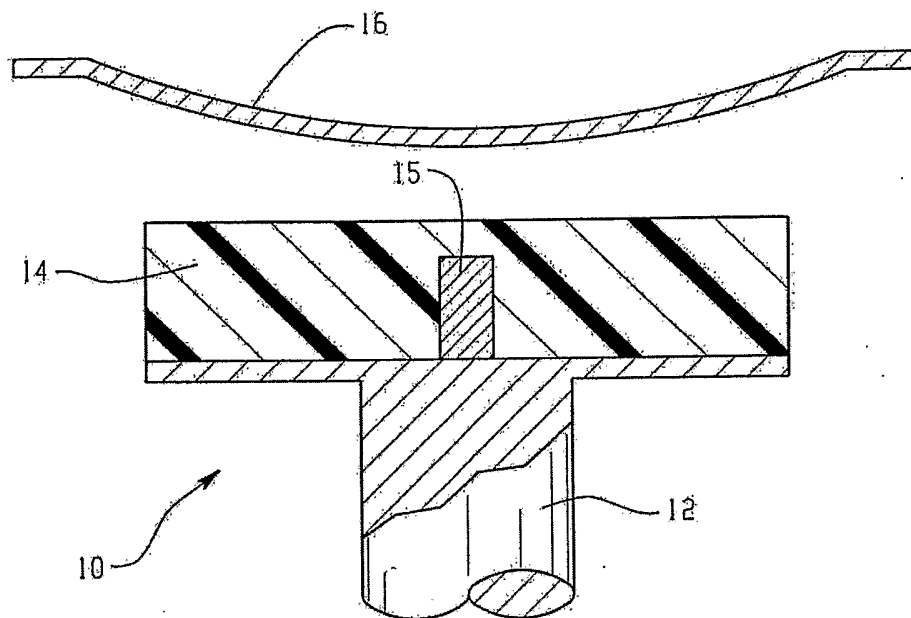
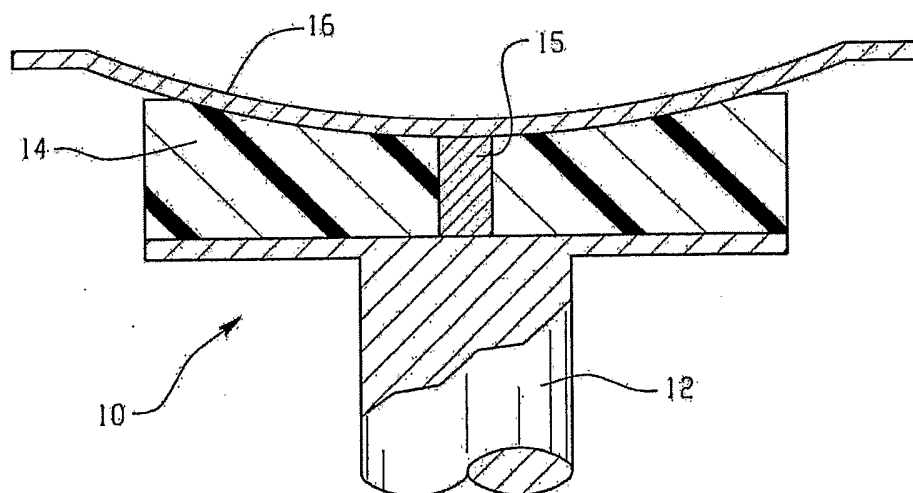
41. The method (50) of Claim 40, wherein the status of the reconfigurable pad (14) determines whether the reconfigurable pad (14) has reached an end of its useful life.

42. The method (50) of any of the preceding Claims, further comprising setting (54) a flag when an end of life condition is met for the reconfigurable pad (14), and replacing or repairing the reconfigurable pad (14).

43. The method (50) of any of the preceding Claims, wherein determining (58) if the reconfigurable pad (14) needs to be reconfigured further comprises training (60) the reconfigurable pad (14) to conform to a surface contour of the workpiece (16).

44. The method (50) of any of the preceding Claims, wherein determining (58) if the reconfigurable pad (14) needs to be reconfigured further comprises training (60) the reconfigurable pad (14) to conform to a surface contour of a master.

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*Fig. 1**Fig. 2*

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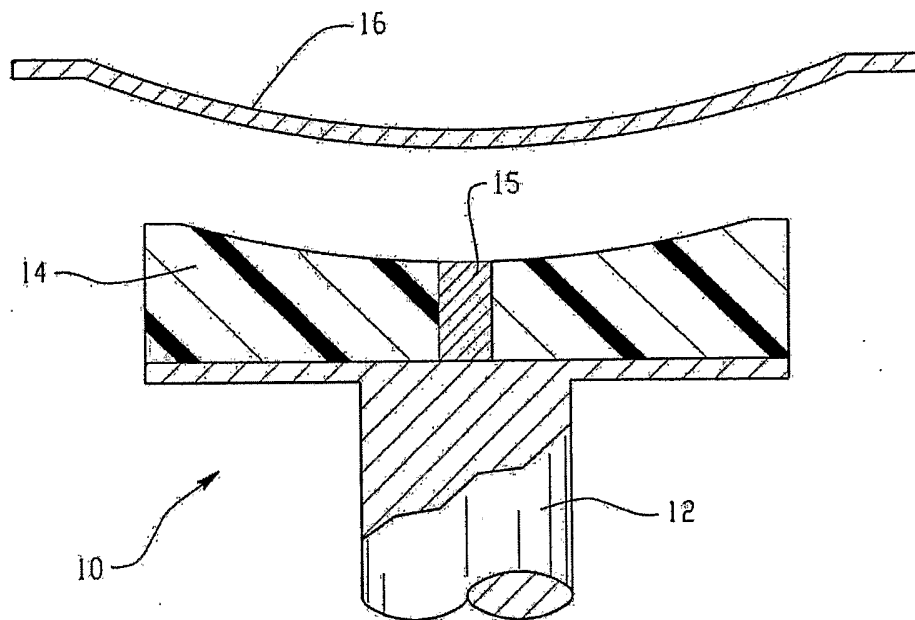


Fig. 3

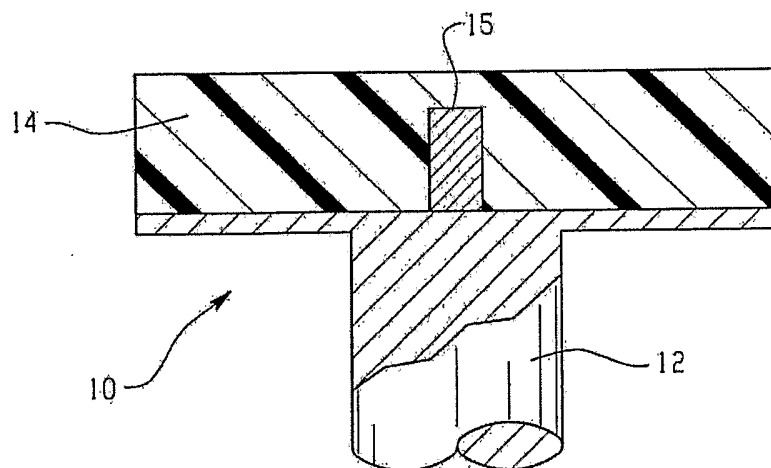


Fig. 4

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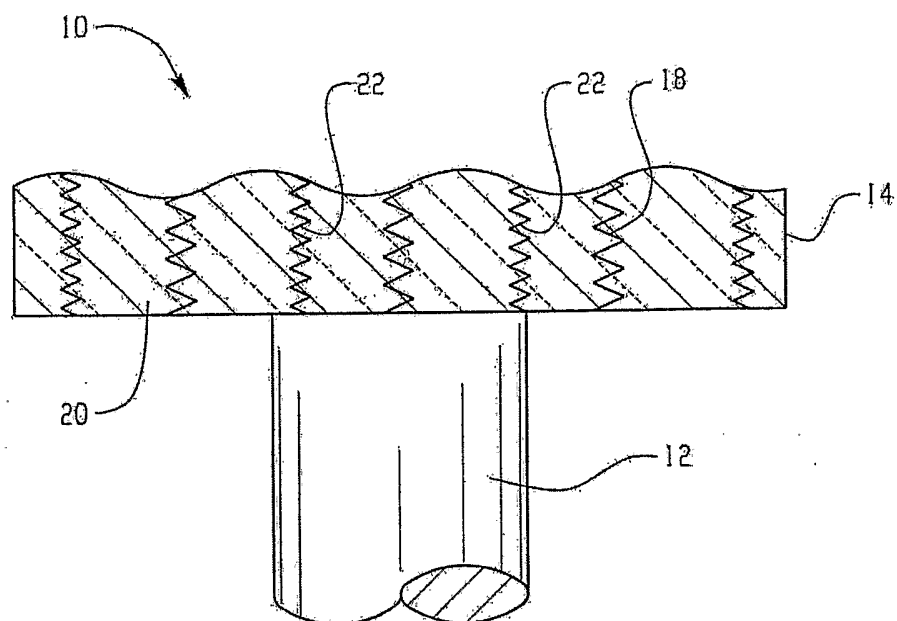


Fig. 5

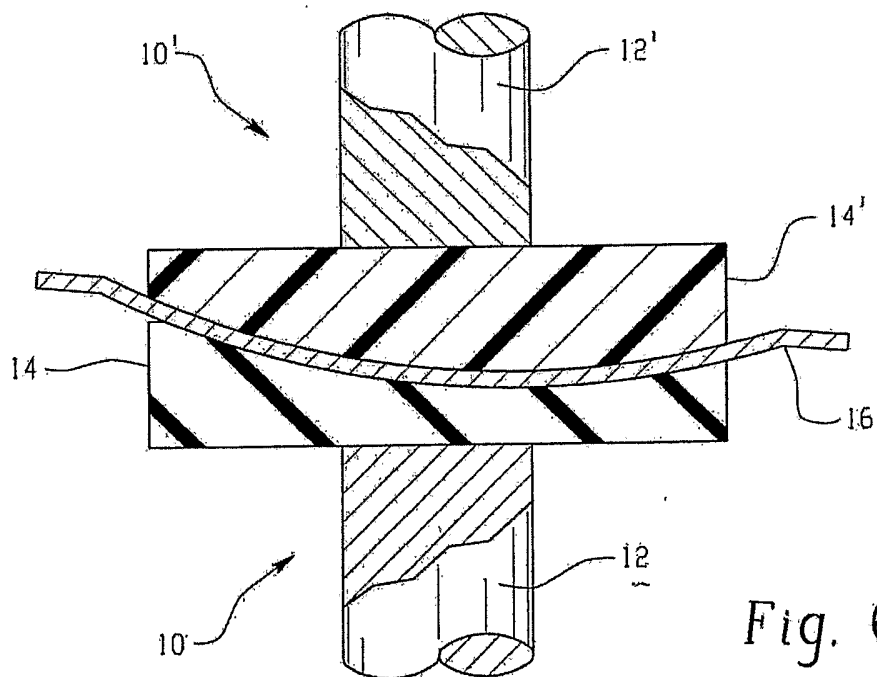


Fig. 6

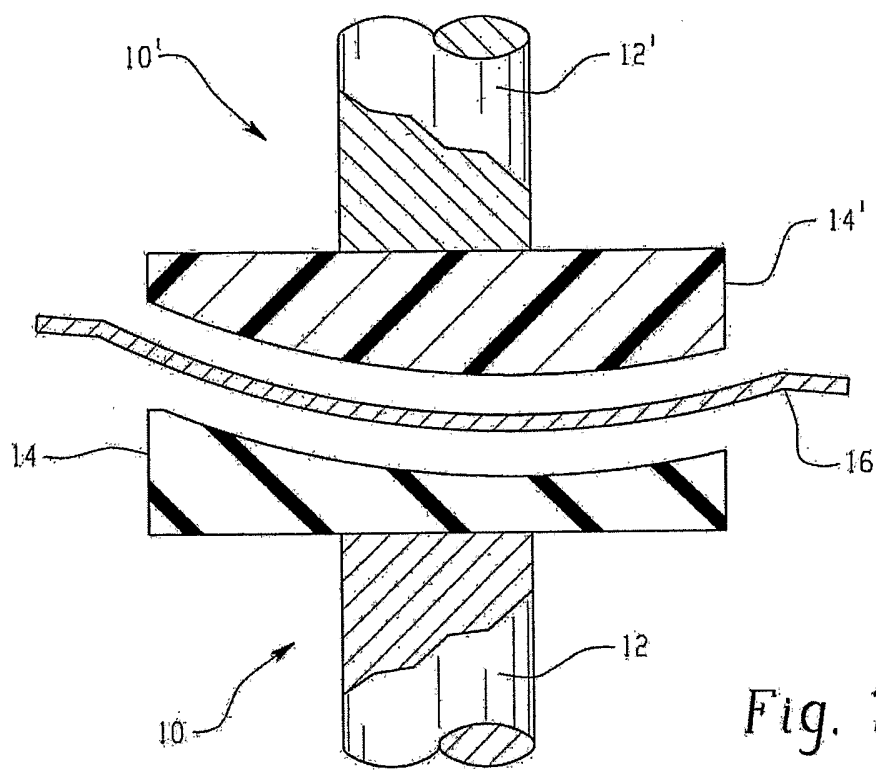


Fig. 7

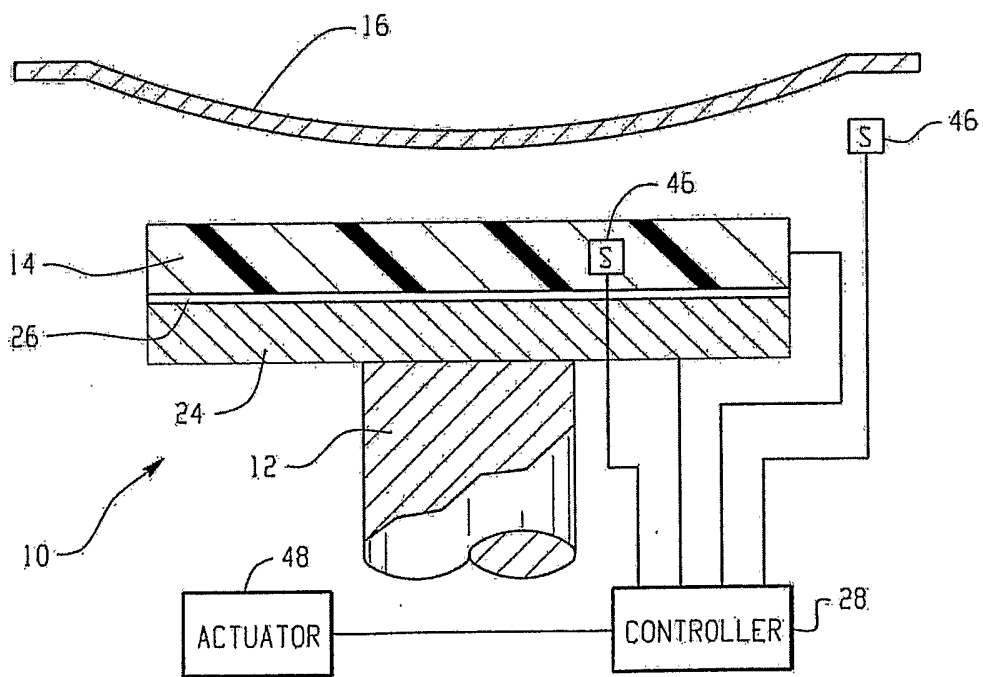


Fig. 8

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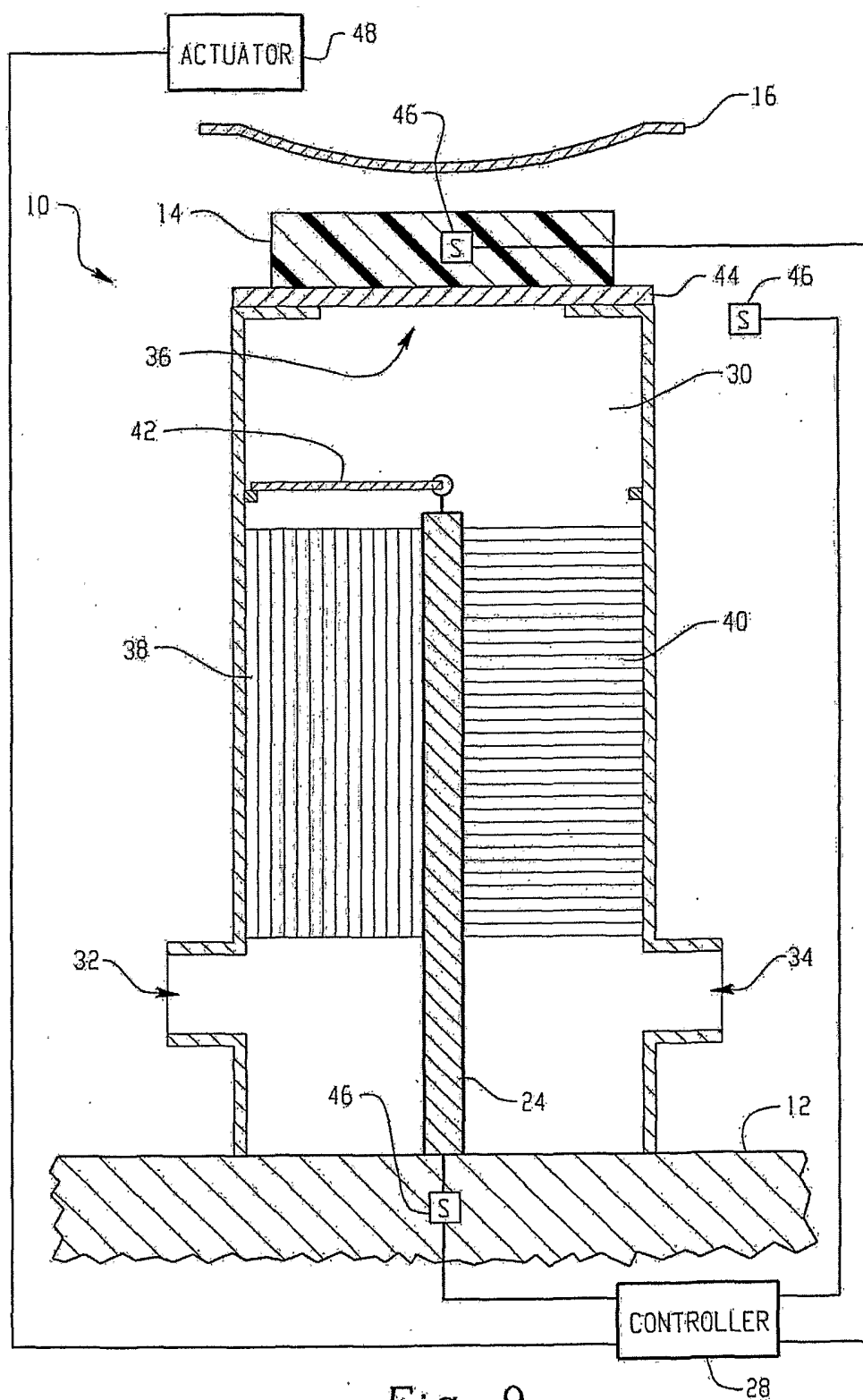


Fig. 9

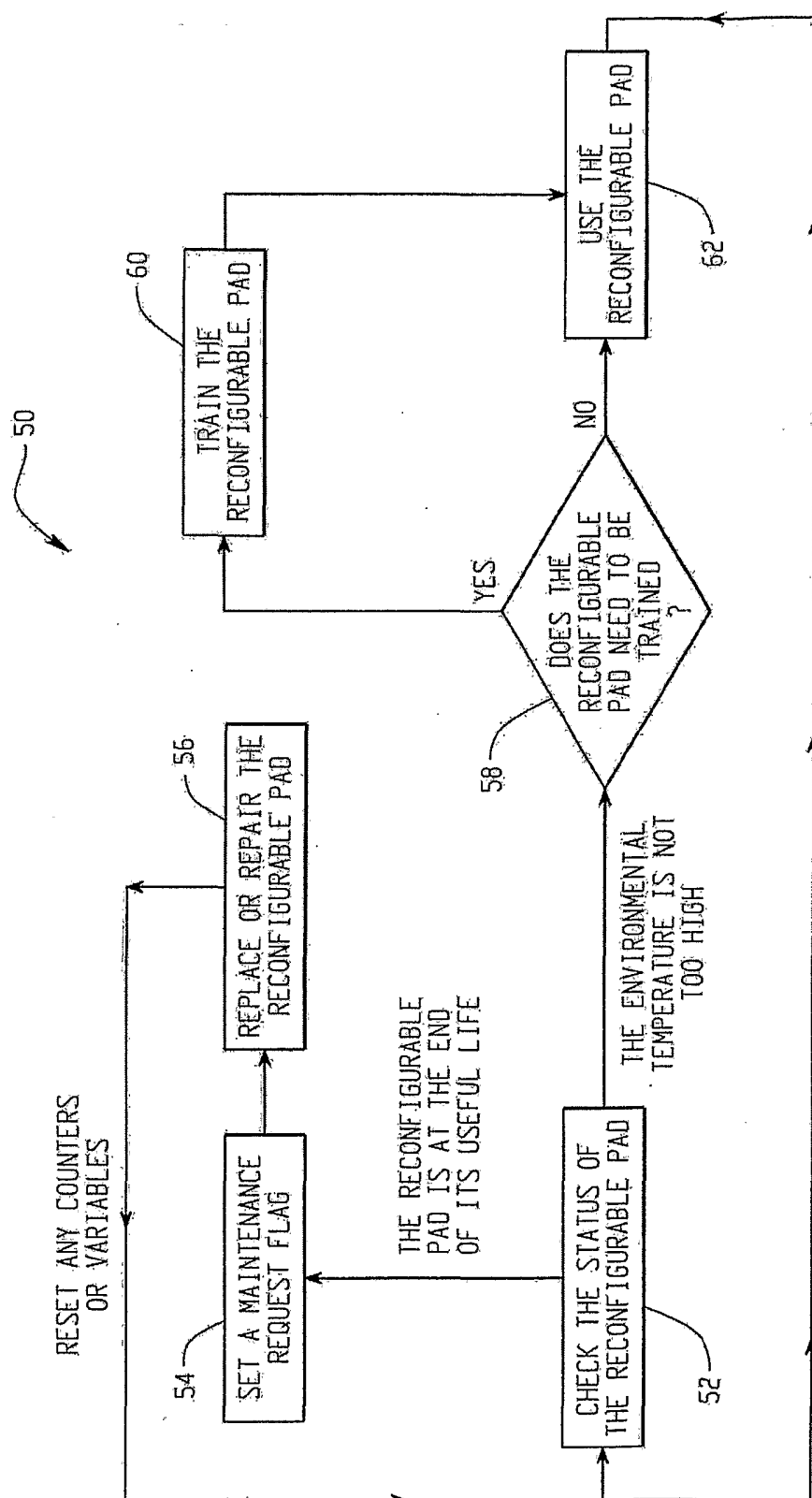


Fig. 10